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<p><b>(54) Title:</b> SEMICONDUCTOR CONNECTION COMPONENTS AND METHODS WITH RELEASABLE LEAD SUPPORT</p> <p><b>(57) Abstract</b></p> <p>A connection component for electrically connecting a semiconductor chip to support substrate incorporates a preferably dielectric supporting structure (70) defining gaps (40). Leads extend across these gaps so that the leads are supported on both sides of the gap (66, 70). The leads therefore can be positioned approximately in registration to contacts on the chip by aligning the connection component with the chip. Each lead is arranged so that one end can be displaced relative to the supporting structure when a downward force is applied to the lead. This allows the leads to be connected to the contacts on the chip by engaging each lead with a tool and forcing the lead downwardly against the contact. Preferably, each lead incorporates a frangible section (72) adjacent one side of the gap and the frangible section is broken when the lead is engaged with the contact. Final alignment of the leads with the contacts on the chip is provided by the bonding tool which has features adapted to control the position of the lead.</p>		

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SEMICONDUCTOR CONNECTION COMPONENTS AND METHODS  
WITH RELEASABLE LEAD SUPPORT

TECHNICAL FIELD

5           The present invention relates to methods, components and apparatus useful in mounting and connecting semiconductor devices.

BACKGROUND ART

10           Semiconductor chips typically are connected to external circuitry through contacts on a surface of the chip. The contacts on the chip typically are disposed in the regular patterns such as a grid substantially covering the front surface of the chip, commonly referred to as an "area array" or in elongated rows 15 extending along each edge of the chip front surface. Each contact on the chip must be connected to external circuitry, such as the circuitry of a supporting substrate or circuit panel. Various processes for making these interconnections use prefabricated arrays 20 of leads or discrete wires. For example, in a wirebonding process, the chip is physically mounted on the substrate. A fine wire is fed through a bonding tool. The tool is brought into engagement with the contact on the chip so as to bond the wire to the contact. The tool is then moved to a connection point 25 of the circuit on the substrate, so that a small piece of wire is dispensed and formed into a lead, and connected to the substrate. This process is repeated for every contact on the chip.

30           In the so-called tape automated bonding or "TAB" process, a dielectric supporting tape, such as a thin foil of polyimide is provided with a hole slightly larger than the chip. An array of metallic leads is provided on one surface of the dielectric film. These 35 leads extend inwardly from around the hole towards the edges of the hole. Each lead has an innermost end projecting inwardly, beyond the edge of the hole. The innermost ends of the leads are arranged side by side at spacing corresponding to the spacings of the contacts on

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the chip. The dielectric film is juxtaposed with the chip so that the hole is aligned with the chip and so that the innermost ends of the leads will extend over the front or contact bearing surface on the chip. The 5 innermost ends of the leads are then bonded to the contacts of the chip, as by ultrasonic or thermocompression bonding. The outer ends of the leads are connected to external circuitry.

In a so-called "beam lead" process, the chip 10 is provided with individual leads extending from contacts on the front surface of the chip outwardly beyond the edges of the chip. The chip is positioned on a substrate with the outermost ends of the individual leads protruding over contacts on the substrate. The 15 leads are then engaged with the contacts and bonded thereto so as to connect the contacts on the chip with contacts on the substrate.

The rapid evolution of a semiconductor art in 20 recent years has created a continued demand for progressively greater numbers of contacts and leads in a given amount of space. An individual chip may require hundreds or even thousands of contacts, all within the area of the chip front surface. For example, a complex 25 semiconductor chip in current practice may have a row of contacts spaced apart from one another at center-to-center distances of 0.5 mm or less and, in some cases, 0.15 mm or less. These distances are expected to decrease progressively with continued progress in the art of semiconductor fabrication.

30 With such closely-spaced contacts, the leads connected to the chip contacts, must be extremely fine structures, typically less than 0.1 mm wide. Such fine structures are susceptible to damage and deformation. With closely spaced contacts, even minor deviation of a 35 lead from its normal position will result in misalignment of the leads and contacts. Thus, a given lead may be out of alignment with the proper contact on the chip or substrate, or else it may be erroneously

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aligned with an adjacent contact. Either condition will yield a defective chip assembly. Errors of this nature materially reduce the yield of good devices and introduce defects into the product stream. These problems are particularly acute with those chips having relatively fine contact spacings and small distances between adjacent contacts.

It has been proposed to form a prefabricated lead assembly having inwardly projecting leads with all of the inner ends of the leads connected to a common inner element. The common element typically is a metallic ring-like structure. In these structures, the inner end of each lead is connected to the common element via a frangible section. The common element thus restrains the inner ends of the leads against relative movement and hence inhibits bending or other deformation of the leads. After the leads have been bonded to the chip contact, the common element is broken away from the leads. A frangible section may be provided at the juncture between the innermost end of each lead and the inner element. Systems of this nature are illustrated, for example, in Thorpe, Jr. U.S. Patent 4,756,080 and in Angelucci, Sr. et al, U.S. Patent 4,380,042. Burns, U.S. Patents 4,312,926 and 4,413,404 depict a generally similar arrangement in which the leads are multilayer metallic structures including a copper base with an overcoat of nickel. The frangible connection between the innermost end of each lead and the inner element consists solely of the nickel overcoat layer, thereby providing a very thin, weak section.

In these arrangements, the common element electrically interconnects all of the leads. These interconnections must be eliminated after the leads have been bonded to the chip. Thus, the common element must be pulled away from the chip after the leads have been bonded to the contacts of the chip. All of the frangible elements must be broken either simultaneously or in a particular pattern as the common element is

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5 pulled away from the innermost ends of the leads. The need to remove the common element constitutes a significant drawback, inasmuch as this must be done without disturbing the delicate bonds between the lead ends and the contacts on the chip. Perhaps for these reasons, systems utilizing a common element have not been widely adopted.

10 Thus, despite the substantial time and effort devoted heretofore to the problems associated with mounting and connecting of semiconductors, there have still been substantial, unmet needs for improvements in such processes and in the equipment and components used to practice the same.

DISCLOSURE OF THE INVENTION

15 One aspect of the present invention provides a semiconductor chip mounting component. A component according to this aspect of the invention includes a support structure having upper and lower surfaces and having a gap extending through the support structure, so that the gap extends downwardly from the upper surface to the lower surface. The component also includes plural electrically conductive leads. Each lead has a connection section extending across the gap in the support structure. First and second ends of the 20 connection section are secured to the support structure on opposite sides of the gap. The second end of each connection section is secured to the support structure so that the second end can be displaced downwardly relative to the support structure responsive to a downward force applied to the connection section. Each 25 connection section is flexible, so that the connection section can be bent downwardly when the second end of the connection section is displaced downwardly relative to the support structure. Thus, the connection section of each lead will be supported at both ends by the support structure during positioning of the component on a semiconductor chip assembly. However, each connection section can be bent downwardly to engage a contact on a 30 35

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part of the semi-conductor chip assembly after the component has been positioned on the part.

5        Most preferably, the connection sections of the leads are connected to the support structure so that the first end of each such connection section is permanently connected to the support structure, whereas the second end of each such connection section is detachable from the support structure upon application of a downward force to the connection section. The 10        first end of each connection section typically is connected, by a further portion of the lead, to a terminal mounted on the support structure.

15        In a typical arrangement, the component is adapted to be positioned on the chip itself. Thus, when the component is positioned on the chip, the connection sections of the leads will overlie contacts on the chip. The connection sections are bonded to the contacts on the chip. The leads may have terminals remote from the connection sections for connecting the leads, and hence 20        the contacts of the chip, to contacts on a substrate. In the reverse arrangement, the component according to this aspect of the invention may be adapted for positioning on the substrate, with the connection sections of the leads overlying the substrate so that 25        the connection sections can be bonded to the contacts of the substrate. The leads may be connected to the contacts on the chip through terminals remote from the connection sections.

30        Each lead may include a second end securement section attached to the support structure and a frangible section connecting the second end of the connection section with the second end securement section, so that the second ends of the connection sections are attached to the support structure through 35        the frangible sections of the leads. The frangible sections can be broken upon downward displacement of the connection sections. The frangible section of each such lead may have a cross-sectional area smaller than the

cross-sectional area of the second end securement section and smaller than the cross-sectional area of the connection section.

Most preferably, the connection section of each lead defines a pair of opposed edges and the frangible section has a pair of notches extending inwardly from such edges to define a neck having width less from the width of the connection section. In another arrangement, each lead includes a relatively thick structural metal layer and a relatively thin first supplemental metal layer. The connection section and the second end securement section of each lead incorporate the structural metal layer, whereas the frangible section of each lead includes the first supplemental metal layer but omits the structural metal layer. In yet another arrangement, the second end of each connection section may be bonded to the support structures so that the bond may be broken upon downward displacement of the connection section, whereas the first end of each such connection section is permanently bonded to the support structure.

Alternatively, the frangible section of each lead may include a polymeric material. In yet another arrangement, each lead may extend only partially across the gap in the support structure, and the component may incorporate a polymeric strip associated with each lead extending co-directionally with the lead entirely across the gap. Each such polymeric strip may be secured to the support structure on both sides of the gap and the connection section of each lead may be bonded to the associated polymeric strip. In this case, the second end of each connection section is secured to the support structure only through the associated polymeric strip, and the lead can be displaced downwardly relative to the support structure with breakage or elongation of the polymeric strip.

According to a further aspect of the invention, the component may include a flexible,

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continuous polymeric reinforcement in contact with each lead at an edge of the support structure so that the polymeric reinforcement will inhibit stress concentration in the lead at such edge when the lead is 5 bent downwardly to engage a contact. Most preferably, the polymeric reinforcement associated with each lead includes a polymeric strip as discussed above overlying the connection section of the lead. Desirably, the 10 polymeric strips associated with the various leads are integral with a polymeric layer of the support structure.

Most preferably, the support structure is formed from dielectric materials such as polymeric materials, so that the support structure does not 15 electrically interconnect the leads with one another. The support structure may have appreciable thickness, i.e., an appreciable distance between its upper and lower surfaces. The leads may be disposed at an appreciable distance above the lower surface of the 20 support structure. For example, the support structure may include a plurality of layers with a top layer defining the upper surface of the structure and a bottom layer defining the lower surface. The leads may be disposed above the bottom layer. Alternatively, the 25 component may be supported above the chip during the mounting process. In either case, each connection section is supported above the front surface of the chip by the support structure before such connection section is displaced downwardly to engage a contact. The 30 component may include terminals disposed on the support structure. In a particularly preferred arrangement, the terminals, as well as the leads are disposed above a bottom layer and the bottom layer is resilient so as to permit downward displacement of the terminals.

35 The gap in the support structure may be formed as an elongated slot. The connection sections of many leads may extend across such slot. The connection sections extending across each such slot are disposed in

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5 side-by-side, substantially parallel arrangement. In a particularly preferred arrangement, the component further includes an elongated bus extending on the support structure alongside each elongated slot and the  
10 releasable or second end of the connection section of each lead extending across the slot is connected to the bus by a frangible element. Preferably, each lead includes a frangible section and the bus, the frangible section and the connection section of each lead are formed integrally with one another. Each lead may also include a second and securement section disposed between the frangible section and the bus.

15 Typically, the bus, as well as the leads, are formed from one or more metallic materials. The bus serves to reinforce the support structure and leads, and maintain even more accurate positioning of the leads when the component is assembled to a chip. Moreover, during manufacture of the component, the bus can be used to provide electrical conductivity for plating processes  
20 as, for example, in formation of terminals.

25 In a particularly preferred arrangement, the gap in the support structure may include a plurality of elongated slots. The support structure may have a central portion and a peripheral portion, and the slots may extend substantially around the central portion so that the slots are disposed between the central portion and the peripheral portion. A bus as aforesaid may be provided alongside each slot, desirably on the peripheral portion, so that one such bus extends  
30 alongside each slot. Preferably, the slots are connected to one another to form a substantially continuous channel surrounding the central portion, leaving the central portion of the support structure connected to the peripheral portion only through the leads. All of the buses may be connected to one another  
35 so that the buses cooperatively form a hoop-like structure on the peripheral portion, substantially surrounding the slots and the central portion. In such

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an arrangement, the first or permanently connected end of the connection section of each lead faces towards the central portion of the support structure and is electrically connected to a terminal on the central portion. During the connection process, the frangible sections of the leads are broken so that the leads are detached from the peripheral portion, thereby detaching the central portion from the peripheral portion and leaving the peripheral portion connected to the chip. At the same time, the leads are electrically disconnected from the buses.

In an alternative arrangement, some of the leads associated with each slot may have their first or permanently mounted ends disposed at a first edge of the slot and their second or releasably connected ends disposed a second edge of the slot, whereas the remaining leads associated with the same slot may have the reverse arrangement, i.e., the first end of the lead disposed at the second edge of the slot and the second end of the lead connection section disposed at the first edge of the slot. According to a further alternative, the gaps in the support structure may be relatively small holes extending through the support structure. One lead, or a few leads, may extend across each such hole. There may be numerous holes disposed at various locations on the support structure. For example, the holes, and the leads, may be disposed in an array substantially covering the top and bottom surfaces of the support structure as, for example, where the component is to be used with a chip or other element having contacts in a "area array" on substantially the entirety of its front surface.

A further aspect of the invention provides methods of making connections to contacts on a part of a semiconductor chip assembly, such as to contacts on a front surface of a semiconductor chip or contacts on a chip mounting substrate. Methods according to this aspect of the invention desirably include the steps of

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juxtaposing a connection component, such as a component described above, with the part so that a bottom surface of the support structure in the component faces downwardly, towards the surface of the part and the top surface of the connection component faces upwardly, away from the front surface of the part. The connection component is juxtaposed with the part so that each contact on the part surface is aligned with a gap in the support structure and so that connection sections of leads extending across the gap are disposed above the contacts. The support structure supports each connection section at both sides of each such gap during the juxtaposing step, so that the connection section does not tend to bend or deform at this stage of the process.

The method desirably further includes the step of bonding each connection section to a contact on the part by displacing each connection section downwardly so as to displace one end of each such connection section downwardly relative to the support structure and bring the connection section into engagement with the contact of the part. Preferably, the bonding step is performed so as to detach one end of each connection section from the support structure during the downward displacement of the connection section as, for example, by breaking a frangible portion of each lead or detaching a bond between the lead and the support structure as discussed above. In a particularly preferred arrangement, the support structure has a gap in the form of one or more elongated slots and buses along the slots serve to reinforce the support structure prior to and during the connection step. As also discussed above, the gap in the support structure may surround a central portion of the support structure so that the central portion is initially attached to the peripheral portion only through the leads, and the connection step may serve to sever the central portion from the peripheral portion.

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5        The bonding step most preferably includes the step of engaging each connection section with a recess in a bonding tool so that the bonding tool at least partially controls the position of the connection section in lateral directions transverse to the downward travel of the bonding tool.

10      The use of the bonding tool to guide and constrain the lead during the bonding step may be applied even where the connection component does not have the connection sections connected to the support structure at both ends. Thus, the step of guiding the connection section of the lead with the bonding tool may be employed even where the leads are cantilevered from an edge of the support structure. Most preferably, the 15     methods according to this aspect of the invention further include the step of aligning the bonding tool with the contacts on the part, such as with contacts of a semiconductor chip. Preferably, the step of engaging the bonding tool with the leads is performed so that the 20     bonding tool actually brings the leads into alignment with the contacts. That is, the contact sections of the leads may be slightly out of alignment with the contacts, but the bonding tool moves the leads in directions transverse to the leads as the bonding tool 25     is engaged with the leads, thereby bringing each lead into alignment with the contacts. Thus, it is unnecessary to achieve exact alignment between the connection sections of the leads and the contacts on the part when the connection component is first applied to 30     the part. Any slight misalignment will be corrected by action of the bonding tool.

35      In one arrangement, each connection section is an elongated, strip-like structure and the bonding tool has an elongated groove or recess in its bottom surface. The bonding tool is positioned above each contact so that the groove or recess extends in a pre-selected groove direction and extends across the top of a contact. The connection sections of the leads extend

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generally parallel to the groove direction, so that when the bonding tool is advanced downwardly to engage the lead, the connection section of each lead is seated in the groove. If the lead is slightly out of alignment 5 with the groove, the lead will be moved in lateral directions, transverse to the groove, until it seats in the groove and thus becomes aligned with the contact.

Yet another aspect of the present invention provides a tool for bonding leads to contacts on a 10 semiconductor chip, substrate or other part of a semiconductor chip assembly. A tool according to this aspect of the invention desirably includes a generally body defining a bottom and a groove extending in a lengthwise direction along such bottom for engaging 15 leads to be bonded. The tool desirably also includes means for connecting the tool to a bonding apparatus so that the bottom of the tool faces downwardly. Such a tool can be used in methods as aforesaid. Most preferably, the groove has a central plane and surfaces 20 sloping upwardly from the sides of the groove towards the central plane. These sloping surfaces will tend to guide a lead engaged with the tool towards the central plane of the groove.

Yet another aspect of the invention provides 25 methods of making semiconductor connection components. Methods according to this aspect of the invention include the steps of providing one or more conductive leads, each lead having an elongated connection section. The method further includes the step of treating a 30 dielectric support structure in contact with the leads so that the support structure incorporates one or more gaps aligned with the connection sections of the leads and so that each lead is permanently secured to the support structure at one end of the connection section 35 and releasably secured to the supporting structure at the other end of the connection section. The leads may be provided on a sheet-like dielectric support layer and may be supported by such layer. The step of forming the

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support structure may include the step of selectively removing a part of the dielectric layer to form a gap therein in alignment with the connection sections of the leads.

5                   The step of providing the leads may include the step of forming each lead with a fragile section in the connection section. Thus, the leads may be formed by plating an electrically conductive material such as a metal, preferably gold, to form elongated strips of a preselected width with frangible sections of a lesser width. Where the component is to be provided with elongated buses as discussed above, the buses may be formed by plating at the same time as the leads. The dielectric layer may be formed from a polymeric material 10 such as polyimide and the step of selectively removing a portion of the dielectric layer may be performed after forming the strips. That is, the strips are deposited on the dielectric sheet and the dielectric sheet is then etched or otherwise selectively treated so as to form 15 the gap or gaps. After formation of the gap or gaps, one end of each connection section remains connected to the dielectric sheet through the frangible section, and hence is releasably connected to the dielectric sheet. Alternatively, the leads may be formed by providing 20 strips of a conductive structural material so that each such strip has an interruption therein, and depositing a first supplemental material so that such supplemental material overlies each strip at least in a zone of the strip including the interruption, so as to leave 25 portions of the strip on opposite sides of the interruption connected to one another by the first supplemental material. Thus, the frangible section of each lead may include a section formed from the supplemental material. The structural material and the 30 supplemental material may both be metals and the supplemental material may be applied as a thin layer in a plating process before treating the dielectric material to form the gaps.

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Alternatively, the leads may be formed by depositing strips of a conductive material, without frangible sections, on the dielectric sheet and then etching the dielectric sheet to form the gap or gaps.

5 The dimensions of the gap or gaps so formed are controlled so as to leave each lead with a relatively large first end securement section bonded to the dielectric sheet on one side of the gap and with a relatively small, second end securement section bonded to the sheet on the other side of the gap, so that the 10 end of each lead adjacent such other section can be detached from the dielectric sheet by breaking this relatively small bond. In this instance, there is no need to form a frangible section in each lead.

15 The foregoing and other objects, features and advantages of the present invention will be more readily apparent from the detailed description of the preferred embodiments set forth below, taken in conjunction with the accompanying drawings.

20 BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 is a diagrammatic plan view of a semiconductor connection component in accordance with one embodiment of the invention.

25 Figure 2 is a fragmentary, diagrammatic, partially sectional view depicting a portion of the component illustrated in Figure 1.

Figure 3 is a diagrammatic, fragmentary, sectional view on an enlarged scale taken along line 3-3 in Fig. 2.

30 Figure 4 is a diagrammatic plan view of a chip and another element used with the component of Figs. 1-3.

35 Figure 5 is a view similar to Fig. 2 but depicting the component of Fig. 2 in conjunction with the components of Fig. 4 during an assembly process.

Figure 6 is a diagrammatic side elevational view of a tool utilized in the assembly process of Fig. 5.

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Figure 7 is a diagrammatic end elevational view of the tool depicted in Fig. 6.

5 Figure 8 is a fragmentary, sectional view on an enlarged scale depicting portions of the tool of Fig. 6 and the components of Figs. 1-5 during the assembly process.

10 Figure 9 is a view similar to Fig. 2 but depicting portions of a component in accordance with a further embodiment of the invention.

15 Figure 10 is a fragmentary, sectional view depicting portions of a component in accordance with yet another embodiment of the invention.

15 Figure 11 is a fragmentary, sectional view depicting the component of Fig. 10 in conjunction with a semiconductor chip after an assembly process.

Figure 12 is a fragmentary, plan view depicting the component of Fig. 10.

20 Figures 13 and 14 are fragmentary, sectional views similar to Figs. 10 and 11 respectively but depicting a component in accordance with yet another embodiment of the invention.

Figure 15 is a view similar to Fig. 2 but depicting a component in accordance with a further embodiment of the invention.

25 Figure 16 is a fragmentary, partially sectional perspective view depicting the component of Fig. 15 and a chip after an assembly process.

30 Figure 17, 18 and 19 are fragmentary, diagrammatic sectional views depicting additional components in accordance with further embodiments of the invention.

Figures 20A through 20G are diagrammatic sectional views depicting a fabrication process in accordance with an embodiment of the invention.

35 Figures 21A through 21H are diagrammatic sectional views similar to Figures 20A through 20G but depicting another fabrication process in accordance with another embodiment of the invention.

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Figure 22 is a diagrammatic perspective view illustrating an assembly incorporating a component according to yet another embodiment of the invention.

5 Figure 23 is a diagrammatic view depicting a plurality of components in accordance with yet another embodiment of the invention.

Figure 24 is a diagrammatic plan of view on an enlarged scale depicting portions of one component illustrated in Fig. 23.

10 Figure 25 is a fragmentary sectional view depicting a portion of the component of Fig. 24 together with other elements.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

15 A semiconductor connection component in accordance with one embodiment of the invention has a supporting structure 30 incorporating a flexible top dielectric layer 32 and a bottom, compliant dielectric layer 34 (Fig. 2). Body 30 is generally sheet-like and has a top surface 36 defined by top layer 32 and a bottom surface 38 defined by bottom layer 34. The terms 20 "top" and "bottom" are used herein to indicate directions relative to the structure of the connection component itself. It should be understood as referring to the frame of reference of the component itself, and not to the ordinary, gravitational frame of reference. 25 Likewise, the terms "upwardly" and "downwardly" should also be understood as referring to the frame of reference of the component itself. Top layer 30 may be about 0.01 to about 0.1 mm thick, whereas bottom layer 34 may be about 0.05 to about 1.0 mm thick. Support structure 30 may be formed as part of a large, 30 substantially continuous strip-like tape 33 containing a plurality of such support structures.

Support structure 30 has four gaps 40 in the 35 form of elongated slots extending through the support structure, from the top surface 36 to the bottom surface 38. The gaps or slots 40 subdivide structure 30 into an interior portion 42 substantially bounded by the gaps 40

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and four strip-like outer securement elements 44 disposed outside of the gaps, the securement elements 44 being connected to the central portion 42 by bridge elements 46. As best seen in Fig. 1, the gaps or slots 5 40 define a generally rectangular pattern, with the slots defining the edges of the rectangle and the bridge elements 46 being disposed at the corners of the rectangle.

The component also includes a plurality of 10 central terminals 48 disposed on the central region 42 of the support structure and a plurality of outside terminals 50 disposed on the securement elements 44. For clarity of illustration, the drawings depict only a 15 relatively small number of central terminals 48 and outside terminals 50. In actual practice, however, there may be hundreds or even thousands of terminals. Each central terminal 48 is associated with a central terminal lead 52, whereas each outside terminal 50 is associated with an outside terminal lead 54. As best 20 seen in Fig. 2, each central terminal 48 is disposed between top layer 32 and bottom layer 34 on the central region 42 of the support structure. Each of the 25 terminals 48 is exposed at the top surface of the component, through apertures in the top dielectric layer. The central terminal lead 52 associated with each such central terminal 48 is formed integrally with that central terminal and extends from it towards the periphery of the support structure, outwardly across one 30 of the slots 40. Each central terminal lead thus includes an elongated connection section 56 extending across the associated gap or slot 40. A first end 58 of each such connection 56 lies at the first side 60 of the slot 40, at the central region 42, whereas the second end 62 of each such connection section 56 lies adjacent the second, opposite side 64 of the slot, adjacent the 35 securement element 44. Each central terminal lead 52 also includes a first end securement section 66 extending from the associated terminal 48 to the first

end of the connection section. The first end securement section and the connection section of each such lead merge with one another at first edge 60 of gap 40. Each central terminal lead also includes a second end securement section 70 attached to the securement structure 44 on the second side of slot 40. Each central terminal lead 52 also includes a frangible section 72 disposed between the second end 62 of the connection section 56 and second end securement section 70.

As best seen in Fig. 3, each central terminal lead includes a structural metal layer 74, a first supplemental metal layer 76 above the structural metal layer 74 and a second supplemental metal layer 78 below the structural metal layer 74. All of these layers are present throughout the entirety of each central terminal lead 52, except that the second supplemental layer 78 and the structural metal layer 74 are interrupted at the frangible section 72. Stated another way, the frangible section 72 consists only of the first supplemental layer 76. Thus, the connection section 56 includes all three metal layers 74, 76 and 78, as does the second end securement section 70, whereas the intervening frangible section 72 includes only the first supplemental layer 76. The supplemental metal layers are substantially thinner than the structural metal layer 56. The frangible section has a groove or notch 80 extending across the lead. As best appreciated with reference to Fig. 2, the groove or notch 80 of each such frangible section 72 is transverse to the direction of elongation E of the connection section 56. Because each such frangible section 72 consists only the first supplemental metal layer 76, the cross-sectional area of the lead in the frangible section 72 is substantially less than the cross-sectional area of the connection section 56 and less than the cross-sectional area of the second end securement section 70. As used in this disclosure, references to the "cross-sectional" areas of

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the leads should be understood as referring to the cross-sectional area in an imaginary cutting plane, such as cutting plane 82, transverse to the elongation direction of the lead, i.e. the cross-sectional area of the lead portion in question seen when viewing in the elongation direction E (Fig. 2).

Structural metal layer 74 (Fig. 3) desirably is about 0.01 mm to about 0.05 mm thick, whereas each of the supplemental metal layers 76 and 78 desirably is about 1 micron to about 75 microns thick. In each case, the thickness is measured in the vertical direction. The width W of the connection section 56 in the horizontal direction transverse to the thickness of the lead and transverse to the direction of elongation E of the connection section desirably is between 0.025 and about 0.25 mm. The frangible section 72 has substantially the same width but a very small thickness, equal only to the thickness of the first supplemental layer 76.

Typically, the supplemental metal layers are applied as platings or coatings on the structural metal layer 56. Structural metal layer 74 preferably is formed from a metal selected from the group consisting of copper, platinum, gold, nickel, aluminum, silver, alloys of these metals with other metals and combinations of such metals and alloys. Of these, silver generally is less preferred whereas gold is more preferred. The supplemental metal layers may be formed from metals selected from the same group. Gold, nickel and copper are particularly preferred as supplemental metal layers. Typically, the supplemental metal layers are formed from a different metal than the structural metal layer.

The outside terminal leads 54 are identical to the central terminal leads 52 except that the positions of the various elements in the outside terminal leads are reversed. Thus, each outside terminal lead 54 has a connection section 86 extending across one of the slots

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40. The first end 88 of each such connection section 86 is disposed adjacent the second edge 64 of slot 40, i.e., adjacent the securement element 44, whereas the second end 90 of each such connection section is 5 disposed adjacent the first edge 60 of the slot and hence adjacent the central region 42 of the securement structure. The first end securement section 92 of each outside lead 54 is mounted to the securement element 44, whereas the second end securement section 94 of each 10 such lead is mounted to the central region 42 of the support structure. Each outside terminal lead is provided with a frangible section 96 disposed between its second end securement section 94 and the second end 15 90 of its connection section 86. The widths and thicknesses of the various elements in each outside lead are identical to those of the central terminal leads discussed above.

The connection sections 56 and 86 of the various leads extend across each slot 40 in a generally 20 side-by-side array. Thus, the elongated connecting portions of the various leads associated with each gap or slot 40 extends substantially parallel to one another. The elongation directions of all of these connecting portions associated with each slot are 25 substantially transverse to the direction of elongation of the slot itself. The spacings between adjacent connection sections are selected so that the center-to-center distances between connection sections are equal to the center-to-center distances between contacts on 30 the chip to be connected. Thus, the center-to-center distances between adjacent connection sections 56 and 86 in a given slot 40, measured in the lengthwise direction of the slot, transversely to the directions of elongation of the connection sections may be about 0.5 35 mm or less and may preferably be about 0.25 mm or less. Also, the dimensions of support structure 30, including the distances between slots 40 are likewise selected to match the distances between contact rows on the chip.

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The connection component discussed above with reference to Figs. 1-3 may be utilized in conjunction with a semiconductor chip 98 seen in Fig. 4. Chip 98 may be a conventional semiconductor chip generally in the form of a rectangular solid having a generally planar front surface 99 with four rows 100 of electrical contacts 102 disposed on such front surface adjacent the edges thereof. The contacts in each such row are disposed along the longitudinal axis 140 of the row. As further discussed below, a generally rectangular collar or supporting ring 104, having a generally planar front or top surface 106 may be employed in conjunction with chip 98. Ring 104 is dimensioned so as to closely surround chip 98. Also, ring 104 has the same thickness as chip 98, so that the top surface 106 of the ring will lie substantially flush with the front surface 99 of the chip when the ring and the chip are disposed on a flat supporting structure.

In one assembly process according to an embodiment of the invention, chip 98 and ring 104 are disposed on a flat surface (not shown) in the orientation illustrated in Fig. 4. The connection component is disposed atop the chip and ring as shown in Fig. 5, with the bottom surface 38 of the connection component support structure facing downwardly and abutting the top surfaces 99 and 106 of the chip and ring and with the top surface 36 of the connection component support structure facing upwardly, away from the chip. The slots or gaps 40 in the connection component support structure are substantially aligned with the rows of contacts 102 on the chip, one such aligned slot 40 and contact row 100 being illustrated in Fig. 5. Thus, the lengthwise direction of each slot extends generally parallel to the lengthwise axis 140 of the aligned row of contacts, whereas each of the connection sections 56 and 86 extending across such slot extend transverse to such lengthwise axis.

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The connection component may be placed on the chip using conventional automatic pattern recognition systems and automatic positioning elements to assure the desired placement of the connection component relative to the chip. Thus, the pattern recognition equipment is linked to a feedback system for controlling either the position of the chip or the position of the connection component so as to align the slots or gaps 40 with the rows of contacts on the chip, and to bring the connection sections of the individual leads into alignment with the correct contacts 102 themselves. Automatic positioning equipment and methods *per se* are well-known and hence need not be described further herein. Despite such automatic positioning equipment and methods however, there will still be some misalignment between the connection sections and the contacts. For example, tolerances on the size and shape of the connection component may result in some individual leads being slightly misaligned with the associated contacts on the chip even when other leads are perfectly aligned. It is difficult to achieve perfect alignment of the connection sections of all the leads and all of the contacts on the chip by adjusting the relative positions of the entire connection component and chip. Preferably, however, any misalignment of an individual lead connection section and the associated contact in the lateral or width-wise directions of the connection section amounts to less than about one-half the center-to-center distance between adjacent connection sections, i.e., less than about one-half of the spacing between adjacent contacts on the chip. Thus, the connection sections of the individual leads at this stage of the process are crudely aligned with the contacts in the lateral directions. Positioning of the connection sections relative to the contacts on the chip in the elongation directions is considerably less critical. Because the connection sections are elongated, each elongation

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5 section may be displaced from its nominal position relative to the associated contact on the chip by a considerable amount, up to about one-half the length of the connection section, while still leaving a portion of the connection section in an appropriate position for engagement with the chip contact in subsequent stages of the process.

10 In the next stage of the process, a bonding tool 110 is employed. As best seen in Figs. 6, 7 and 8, bonding tool 110 has a generally flat, blade-like body 112 with a pair of opposed side surfaces 114 (Fig. 7) a pair of vertical edges 116 (Fig. 6) and a lower edge 118 extending between vertical edges 116. The tool has an elongated first groove 120a formed in lower edge 118 and 15 extending inwardly along such lower edge from one vertical edges 116a to a coupling portion 130 adjacent the midpoint of lower edge 118. Groove 120 occupies substantially the entire width of lower edge 118. As best seen in Fig. 8, groove 120 has opposed sides 122 adjacent the opposite faces 114 of body 112, and has surfaces 124 sloping upwardly from sides 122 to the central plane 126 of the groove, midway between sides 122. Groove 120 merges with a vertical groove 128a 20 extending upwardly along the adjacent edge 116a of the body. Groove 128 tapers in depth so that the depth of this groove gradually decreases towards the upper end thereof. The tool has a radius at the corner between lower edge 118 and vertical edge 116a. The grooves 120a and 128a extend around these radii and merge with one 25 30 another at such radii.

35 The tool also has a generally flat coupling portion 130 extending transversely across lower edge 118, from one of the faces 114 to the other, midway between vertical edges 116. Coupling portion 130 defines a bottom surface 131 (Fig. 8) approximately flush with the edges 122 of groove 120a. The bottom surface 131 has small ridges, grooves or other roughening features (not shown). The bottom edge of the

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tool is also provided with a second groove 120b extending lengthwise along the bottom edge 118 from coupling portion 130 to vertical edge 116b, opposite from edge 116a. Groove 120b and edge 116b are similar to groove 120a and edge 116a discussed above. Thus, a vertical groove 128b on edge 116b joins groove 120b. Tool 110 also has a shank 132 extending upwardly from the top of blade-like body 112, the shank having a screw tip 134 and shoulder 136 at its upper end, remote from body 112. These features are adapted to mate with the tool holder 138 of a bonding apparatus so that the tool may be held in an operative position on the apparatus and so that force and energy from the apparatus may be directed downwardly through the tool as discussed below. The screw tip 134 and shoulder 136 are merely illustrative. The exact configuration of the features which hold the tool to the apparatus will vary with the nature of the apparatus employed. Any such features and/or shapes which will allow the tool to meet with the particular bonding apparatus can be employed. Further illustrations of such features include bolt holes in the tool for mating with bolts on the apparatus, bayonet locks, taper locks and/or straight shanks for engagement in a chock or collet.

In the bonding step of the assembly process, the assemblage of the chip 98, ring 104 and the connection component is aligned with the body 112 of tool 110 so that the elongated groove 120 is aligned with a contact 102 on the chip. Such alignment can be achieved by moving the chip and other associated components relative to the bonding apparatus under control of an automatic vision system or other system for monitoring the position of the chip. The tool is oriented so that groove 120 extends substantially transverse to the direction of the row of contacts, i.e., substantially transverse to the lengthwise axis 140 of the contact row (Fig. 5). The groove 120 thus is roughly aligned with the elongation directions E of the

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connection sections 56 and 86 of the connection component leads overlying that particular row of contacts. However, it should be understood that, in this embodiment, the alignment is established between the tool and the chip, and not between the tool and any element of the connection component. Thus, to the extent that the connection section of a particular lead is out of alignment with the associated contact on the chip, in a lateral direction transverse to the direction of elongation of such lead, such lead connection section will be out of alignment with the tool as well. Provided that the connection sections of the leads have been crudely aligned with the contacts as discussed above, however, any minor remaining misalignment will be corrected by the tool itself during the next step.

Once the tool and the contact of the chip are in alignment, the tool is advanced downwardly, in the direction indicated by arrow 142 in Fig. 5, so as to force the connection section of the most closely aligned lead downwardly. As best appreciated with reference to Fig. 8, as the inwardly sloping surfaces 124 of grooves 120a and 120b engage the connection section 56 of a lead, they displace the lead laterally, towards the central plane 126 of the groove and hence into precise lateral alignment with the contact 102. As the tool moves downwardly under the influence of forces applied by the bonding apparatus, it displaces the connection section 56 downwardly relative to the support structure 30 of the connection component. As the second end 62 of the connection section 56 is forced downwardly, frangible section 72 breaks, thereby freeing the second end from the securement element and detaching the same from the support structure. The first end 58 of each such connection section bends downwardly so that the freed connection section can be forced into engagement with the aligned contact 102 by the tool. At the time the second end 62 of each connection section 56 is detached from the support structure, it is already

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engaged with the groove 120 of the tool. At this time, the support provided to the second end of the connection section to prevent lateral displacement is no longer necessary or desirable. As the tool forces the connection section into engagement with the contact 102, heat and/or ultrasonic vibrations may be applied by the bonding apparatus through the tool so as to cause the connection section to bond to the contact. The lower surface 131 of coupling section 130 bears on the connection section of each lead to force it against the contact. Applied vibrations may be directed along the lengthwise dimension of groove 120, and hence generally along the direction of elongation of the connection section. The roughened surface of coupling section 130 aids in coupling the tool to the connection sections of the lead for transmission of vibrations therebetween. In a further embodiment, the coupling section 130 may be arranged to protrude downwardly beyond the adjacent sections of the tool lower edge 118.

After the connection section of one lead has been bonded to a contact, the tool is retracted upwardly and advanced along the direction of the axis 140 of the contact row. The tool is then aligned with the next contact, and the process is repeated. On some repetitions of the bonding operation, the tool will engage the connection sections 86 of the outside terminal leads 84. The tool is operated in the same manner to bond the outside terminal leads. However, the frangible section which breaks is on the opposite side of the slot 40.

Once this bonding process has been performed for all of the leads, the contacts 102 are connected to the central terminals 48 and outside terminals 50 of the securement element. The subassembly is then ready for testing and further use. As discussed in greater detail in co-pending, commonly assigned U.S. Patent Application Nos. 07/586,758, filed September 24, 1990 and 07/673,020 filed March 21, 1991, and in published International

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Application W092/05582, (Application No. PCT/US91/06920), the disclosures of which are hereby incorporated by reference herein, the compliant bottom dielectric layer 34 permits displacement of the terminals 48 and 50 in the vertical direction towards the front surface 99 of the chip and towards the top surface 106 of the ring. This facilitates engagement of a multiplicity of the terminals with a multiplicity of test probes simultaneously. Compliant layer 34 may have the structure shown in said earlier applications. As more fully described therein, the compliant layer may incorporate holes and masses of compliant material, the masses being aligned with the terminals. As described in said co-pending applications, subassemblies incorporating a connection component (also referred to as a "interposer") may be mounted to a substrate such as a circuit panel or semiconductor package. The terminals 48 and 50 of the connection component are connected to contact pads on the substrate. As described in detail in said co-pending applications, the terminals 48 and 50 on the connection component can move relative to the contacts 102 of the chip, typically in directions parallel to the front surface 99 of the chip. This provides compensation for differential expansion and contraction of the chip and substrate.

The connection component shown in Fig. 9 is similar to the component described above. It incorporates a support structure 230 having a flexible top layer 232 and a compliant dielectric bottom layer 234. However, the gaps 240 in the support structure are not formed as elongated slots, but, instead, are formed as individual holes. These holes 240 are substantially equally distributed over the entire surface area of the support structure 240. Each lead 252 is associated with one such hole, and each lead has a connection section 256 extending across such hole. Each such connection section has a first end 258 adjacent one side of the hole, and a second end 262 adjacent the other side of

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the hole. Once again, the first end 258 of the connection section is connected by a first end securement section 266 to a terminal 248, whereas the second end 262 of the connection section is connected to a thin, frangible section 272, which, in turn, is connected to a second end securement section 270 attached to the support structure. Thus, the second end 262 of the connection section is attached to the support structure through the frangible section 272. The terminals 248 on the structure of Fig. 9 protrude above the top layer 232. Essentially any terminal configuration can be employed, provided that the terminals are in electrical contact with the leads.

Components according to this embodiment of the invention can be used in essentially the same way as the components discussed above. These components are employed with chips having contacts disposed in a "area array" of contacts distributed over substantially the entire area of the chip front surface. The connection component is disposed on the chip front surface so that each contact on the chip is aligned with one hole and crudely aligned with the connection section 256 of one lead. A bonding tool as discussed above is advanced into each hole so as to engage the connection section of the associated lead. Once again, the bonding tool is aligned with the contacts on the chip. Engagement of the bonding tool with the connection section serves to bring the connection section into precise alignment with the contact.

A connection component according to a further embodiment of the invention is illustrated in FIG. 10. That component 302 has a support structure incorporating only a single dielectric layer 332 having one or more gaps 340 therein. A lead 352 extends along the underside of layer 332. Lead 352 incorporates a connection section 356 extending across gap 340. A first end securement section 366 of lead 352 is electrically connected to a terminal 348 and is

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permanently bonded to layer 322. First end securement section 366 is disposed adjacent the first end of connection section 356. The second end 362 of connection section 356 is connected to a second end 5 securement section 370 which, in turn, is releasably bonded to the underside of layer 322. Thus, the bond between first end securement section 366 and layer 322 is considerably stronger than the bond between second end securement section 370 and layer 322. Such 10 differences in bond strength may be achieved in several ways. As illustrated in Fig. 12, at least that portion of first end securement section 366 adjacent gap 340 may have a width  $W$  greater than the width  $W$  of the second end securement section 370.

15 The connection components 302 of Fig. 10 is employed in conjunction with a separate underlayer 304. Underlayer 304 consists essentially of a layer of dielectric material having gaps 306. The gaps 306 in underlayer 304 are arranged in a pattern corresponding 20 to the pattern of gaps 340 in the dielectric layer of the support structure in the connection component itself. In use, the underlayer 304 is applied on the front surface of the chip, and connection component 302 is applied on top of the layer 304. Thus, as seen in 25 Fig. 11, when used with the separate bottom layer 304, the connection component 302, and hence the connection sections 356 of the leads are supported above the front surface of chip 308. Once again, while the component is being positioned, the connection sections 356 are 30 supported at both sides of the gaps 340. In the bonding process, a bonding tool as discussed above is employed to force each connection section downwardly, into engagement with the contact 310 of the chip. In this 35 operation, the second end securement section 370 is detached from the dielectric support structure layer 322 of component 302, whereas the first end securement section 366 and hence the first end of connection section 356 remains attached to such layer. Stated

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another way, the second end of each connection section 356 is released from its attachment with the support structure through peeling or breakage of the bond between the second end securement section and the support structure, rather than by breakage of a frangible section in the lead itself. In this arrangement, the lead does not incorporate a frangible section and hence there is no need for the supplemental layers discussed above with reference to Fig. 3.

5 Desirably, the connection section of the lead consists essentially of a metal selected from the group consisting of copper, gold, nickel, silver, aluminum, platinum and combinations thereof, gold and gold alloys being particularly preferred. Essentially pure gold is

10 especially preferred

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The component 402 illustrated in Figs. 13 and 14 is generally similar to the component 302 described with reference to Figs. 10-12. However, the support structure includes both a top layer 422 and a bottom layer 434 permanently connected together. Here again, a connection section of the lead extends across the gap 440 in the top layer of the support structure. The second end of section 456 is connected to a second end securement section 470, which section is releasably bonded to the top layer 422 of the support structure. However, the end of section 470 remote from connection section 456 is, in turn, attached to a further section 472 of the lead. That further section is permanently mounted to the support structure. As seen in Fig. 14, when connection section 456 is displaced downwardly, the second end 462 of the connection section, adjacent one side of the gap, is also displaced downwardly. The second end securement section 470 peels away from the top layer 422 to permit such downward displacement of the second end. In this embodiment, however, the second end 462 of the connection section remains loosely attached to the support structure through the second end securement section and the further section 472. This

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arrangement is generally less preferred than the other arrangements discussed above because the lead will be stretched somewhat during the assembly process, in deforming from the configuration of Fig. 13 to the configuration of Fig. 14. For this embodiment, it is particularly desirable to form the leads from gold, inasmuch as gold has excellent ductility to accommodate the stretching encountered in the assembly process.

The component 502 illustrated in Figs. 15 and 16 has a bottom layer 534 and a top layer 532 similar to those discussed above, the top layer 532 being formed from a polymeric dielectric material, such as polyimide. Here, again, each lead includes a structural metal layer 574, a first supplemental layer 576 overlying the top surface of the structural metal layer 574 and a second supplemental metal layer 578 on the bottom surface of layer 574. This layered metallic structure extends throughout a first end securement section 566 overlying the supporting structure, and also throughout connection section 556 and second end securement section 570. Each lead further includes a polymeric strip 510 formed integrally with the top layer 532 of the support structure. The top surface of the metallic lead structure, i.e., the top surface of the first supplemental metal layer 576 and the underlying top surface of structural layer 574 are generally flat. Each polymeric strip 510 closely overlies the top surface of one such metallic structure and is bonded thereto, so that each such polymeric strip becomes, in effect, part of the underlying lead. As in the component discussed above with reference to Figs. 1-3, the second end 562 of each connection section 556 is attached to the second end securement section 570 of the lead through a frangible section 572. Within each frangible section, the metallic structure is entirely omitted, so that the frangible section consists only of the polymeric strip 510. In a variant of this approach, the topmost or first supplemental layer 576 may be

continued through the frangible section, so that the frangible section incorporates both polymeric strip and the relatively thin supplemental metal layer. In a further variant, one or both of the supplemental metal layers may be omitted. The structural metal layer 574 5 may be entirely omitted in the frangible section 572, or may be formed with a substantially reduced thickness and/or width in such section. The component of Fig. 15, like the component of Figs. 1-3, has leads extending 10 from both sides of the gap 540. Thus, some of the frangible sections 572 are disposed adjacent one side of the gap, whereas others are disposed adjacent the other side of the gap.

The component of Fig. 15 is assembled to a 15 semiconductor chip 590 and ring 592 in substantially the same way as the component of Figs. 1-3. As the connection sections 556 of the various leads are forced downwardly into engagement with the contacts 594 of the chip, the portions of the polymeric strips constituting 20 the frangible sections 572 of the leads break, thereby detaching the second ends 562 of the connection sections 556 from the support structure. In the structure remaining after the leads have been bonded to the 25 contacts (Fig. 16), each lead has a securement section 566 secured to a part of the support structure 530 and the connection section of each lead projects beyond an edge of the support structure. For example, the connection section 556a of one lead projects beyond an 30 edge 541 of the securement structure 530 at one side of gap 540. The securement section 556b of another lead projects into gap 540 from the other side, and hence projects beyond edge 543 on the opposite side of the gap. The projecting connection section of each such lead is flexed downwardly at and adjacent to the 35 associated edge. For example, the connection section 556a is flexed downwardly at edge 541. The polymeric strips 510 and the polymeric top layer 532 of the support structure, formed integrally therewith, serve to

reinforce the downwardly flexed portions of the leads. In particular, the polymeric strips and polymeric top layer reinforce the metallic structures of the lead and protect it from stress concentrations.

5           The embodiment illustrated in Fig. 17 is similar to that described above with reference to Figs. 15 and 16. Here, again, polymeric strips 610 integral with the top layer 632 of the support structure extend across the gap 640. However, the leads do not  
10          have discrete second end securement sections. Rather, the metallic structure in the connection section 656 of each lead terminates at the second end 662 of such connection section remote from the edge 643 of gap 640. Each such second end is secured to the support structure through a portion 612 of the polymeric strip extending from such second end to the support structure. In operation, the portion 612 of the polymeric strip disposed between the second end of each connection section and the support structure breaks when the  
15          connection section of the lead is forced downwardly into engagement with the electrical contact of the chip. In other respects, this structure operates in substantially the same way as that described above with reference to Figs. 15 and 16.

25          The component illustrated in Fig. 18 has connection sections 756 which are cantilevered. That is, these connection sections project beyond edge 741 of support structure 730, but the second ends 762 of such leads, remote from the edge 741 are not connected to the support structure. Stated another way, the projecting connection sections 756 of the leads are attached to the support structure only at their respective first ends 758. Accordingly, this structure does not provide the enhanced alignment action achieved with the other  
30          embodiments in which the second end of the lead is connected to the support structure. However, because each lead incorporates a polymeric strip 710 overlying and bonded to its metallic structure, these leads will  
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have the reinforcement discussed above with reference to Figs. 15, 16 and 17. That is, when the leads are flexed downwardly, the polymeric strips will reinforce the projecting portions of the metallic structure against 5 stress concentration, particularly at and adjacent the edge of the support structure.

The component illustrated in Fig. 19 has the metallic structure of its leads 852, and its terminals 848, disposed on top of the polymeric top layer 832. 10 Strips 810 formed integrally with the polymeric top layer 832 extend outwardly beyond edge 841 beneath the metallic structure of each lead. Thus, the metallic structure of each lead is reinforced at the juncture of connection section 856 and first end securement section 15 866, i.e., at and adjacent the point where the lead crosses the edge 841 of the support structure. Each polymeric strip 810, however, terminates short of the second end 862 of the connection section, so that a portion of the connection section 856 adjacent the 20 second end 862 has an exposed, downwardly facing metallic surface for engagement with the contact (not shown) of the chip. When the component of Fig. 19 is engaged with a chip, the connection section 856 of each lead is flexed downwardly, breaking the frangible 25 section 872 as discussed above. Here again, the polymeric reinforcing strip 810, closely overlying and bonded to the metallic structure of the lead, reinforces the lead against stress concentration, particularly at adjacent edge 841.

30 As will be readily appreciated, the features of the various embodiments discussed above can be combined with one another. For example, the various connection components illustrated and discussed above as including both a top layer and a bottom layer in their 35 respective support structures can be formed without the bottom layer and used with a separate bottom layer similar to that discussed above with reference to Figs.

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10 and 11. Alternatively, the bottom layer can be omitted entirely.

A process for making a connection component incorporating a lead with a frangible section is illustrated in FIGS. 20A-20G. The process starts with a sheet of polyimide or other thin, flexible dielectric material 902. The sheet has holes 904 formed therein at locations where terminals are desired. A thin layer of copper is deposited non-selectively over the entire sheet, so as to form thin copper layers 906 and 908 on the top surface and bottom surface, respectively, of sheet 902, and also to deposit a thin layer of copper 910 extending through the holes 904. Using a conventional photoresist process, a heavy, structural layer of copper, typically about 0.01 mm to about 0.1 mm thick is applied selectively in holes 904 to form plated "barrel" structures 912 and is also applied selectively on bottom layer 908 so as to form elongated strips 914 on the bottom surface of the sheet where conductors are desired. Strips 914 merge with the copper layer 908 on the bottom surface of the sheet. A pattern of photoresist 907 is used in selectively forming strips 914. Resist pattern 907 incorporates a mass of resist 916 covering bottom copper layer 908 at a preselected point along the length of each strip 914. This resist mast 916 thus forms an interruption in each strip 914. However, the elements of strip 914 on opposite sides of this mass are interconnected by a thin web 917 of copper originally part of copper layer 908. A layer of a supplemental metal, in this case gold, is then selectively applied on the same areas as the copper, i.e., on the strips 914 and on barrels 912. In the next stage of the process (Fig. 20B), the photoresist material 907 used in the steps discussed above is removed, and a new photoresist material 920 is non-selectively applied over the entire bottom surface. The top surface of the sheet is then subjected to an etching process of limited duration. The limited etching

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process removes the thin copper layer 906 from top surface of the sheet, but it does not substantially attack the plated barrels 910.

5 In the next stage of the process, a further photoresist 922 is applied to the top surface of the sheet. That photoresist has holes aligned with plated barrels 912, so that the plated barrels are left uncovered. Moreover, top photoresist 922 has spaces 10 924. Those spaces are aligned with the interruptions in strips 914, and hence with the thin webs 917 left in each strip. As seen in Fig. 20C, each such interruption and thin web 917 is disposed adjacent one side of space 15 924. In the next stage of the process (Fig. 20D), a mass of copper is deposited at the top of each plated barrel 912 so as to form a terminal 926. A layer of nickel (not shown) is also deposited over this copper mass.

20 After the terminals 926 have been formed, the assembly is subjected to a polyimide etching step (Fig. 20E). Those areas of the polyimide underlying spaces 924 in the top resist 922 are removed by the etchant so as to form gaps 528 in polyimide layer 906. The gaps are aligned with the interruptions in strips 25 914, and hence aligned with the thin webs 917 bridging these interruptions, each such interruption and thin web being disposed adjacent one side of the gap. The polyimide etching process may be performed using well-known techniques as, for example, laser etching or plasma etching.

30 After the polyimide has been etched, and while the bottom resist layer is still in place, a thin layer 930 of a supplemental material, in this case gold, is applied on strips 914 by plating. Gold layer 930 also covers the thin copper webs 917 extending across the 35 interruption in each strip 914 (Fig. 20F). Thus, gold layer 930 extends across each such interruption. Following deposition of layer 930, the bottom photoresist 920 is stripped from the assemblage, and the

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bottom surface of the assemblage is subjected to a sub-etching process similar to that discussed above. This sub-etching process is sufficient to remove all exposed portions of layer 908, but does not appreciably attack  
5 the gold-covered copper in strips 914. Because thin webs 917 are uncovered at this point, they are removed in the sub-etching process (Fig. 20G). This leaves a structure as discussed above with reference to Fig. 3. Thus, the copper structural material of the strips 914  
10 is covered by the gold supplemental materials on its top and bottom surfaces, and the copper structural material is interrupted at a frangible section adjacent one edge of gap 928. Thus, portions of the copper lead on opposite sides of each such gap are connected to one  
15 another only by a thin web of the gold supplemental material 930.

In the foregoing process, the lead is supported at both ends while forming the frangible section and also while forming the dielectric supporting material to its final configuration, i.e., while forming the gap in the dielectric support layer. In this case, the lead is supported by the dielectric material itself, and the dielectric material is etched away to form the gap. However, a reverse process could also be employed,  
20 wherein the lead is supported at both ends by a photoresist or other temporary layer and the dielectric material is selectively deposited so as to form a structure having a gap aligned with the frangible section of the lead. Conversely, the gap in the dielectric support layer can be formed first, and the lead can be deposited and etched to form the frangible  
25 section. The materials used in the process can be varied, and may include the different structural and supplemental materials discussed above.

30 35 A process for making a connection component having a permanently secured first end securement section and a detachable second end securement section is schematically illustrated in Figs. 21A through 21H.

The process begins with a laminate including a substantially continuous dielectric support layer 1002 of polyimide or another suitable polymer and a thin layer 1004 of copper or other suitable conductive material on the bottom surface on the dielectric support layer 1002. Utilizing conventional masking and selective electroplating techniques, strips of gold or other suitable lead material 1006 are deposited on copper layer 1004 in a side-by-side array. Only one such strip is visible in Fig. 21B. After deposition of the gold strips 1006 and removal of any temporary masking material used for that process, a layer of photoresist 1008 is deposited on the gold strips and copper layer.

Openings 1010 (Fig. 21C) are etched through polyimide layer 1002 and, desirably, through copper layer 1004 as well. One such opening 1010 is provided for each gold strip 1006, so that the top surface of each gold strip is exposed in one such opening. A bump contact is formed within each such opening 1010. As seen in Fig. 21D, each such bump contact includes a mask 1012 of a base metal such as copper in electrical contact with the associated gold strip 1006 and an overlayer 1014 of a solderable, chemically resistant metal such as nickel, gold or alloys thereof. Following deposition of the bump contacts, photoresist layer 1008 is removed and the thin copper layer 1004 is also removed from the underside of polyimide layer 1002 except in the areas covered by gold strips 1006. This electrically isolates the individual gold strips 1006 from one another, leaving the assembly in the condition illustrated in Fig. 21E.

Next, a substantially continuous layer of a relatively soft, compliant solder mask material 1016 is applied on the bottom surface of polyimide layer 1002 and on strips 1006 (Fig. 21F). Using etching processes as discussed above in connection with Figs. 20A through 20G, a gap 1018 is etched into polyimide support layer

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1002 whereas a further gap 1020 is formed in underlayer 1016. As illustrated in Fig. 21E, the gap 1018 in support layer 1002 overlies a connection section or part 1026 of strip 1006 relatively close to one end of the 5 strip. Thus, a relatively long first end securement section 1022 of each strip 1006 remains attached to support layer 1002 on one side of gap 1018 whereas a relatively short second end securement section 1024 remains attached to layer 1002 on the other side of gap 1018. As used with reference to portions of strip 1006, 10 the terms "long" and "short" refer to the lengths of these portions in the direction of elongation of strip 1006, i.e., in the directions from left to right and right to left in Fig. 21G. Merely by way of example, 15 the second end securement section 1024 may be about .025 mm to about .075 mm long, as measured from the adjacent edge 1028 of gap 1018 to the end 1030 of strip 1006 at the second end securement section. The first end securement section 1022 desirably is longer than the 20 second end securement section. Thus, the first end securement section 1022 may be at least about 1.25 mm long, as measured from the adjacent edge 1032 of gap 1018 to the end 1034 of strip 1006 bounding the first end securement section 1022. The bump contact 1012 1014 25 is disposed on the first end securement section 1022.

The gap 1020 in underlayer 1016 is slightly larger than the gap 1018 in dielectric support layer 1002. Gap 1020 is partially aligned with gap 1018 so that gap 1020 encompasses the connection section 1026 of the strip and also encompasses the second end securement section 1024. Thus, the first end securement section 1022 remains engaged between underlayer 1016 and support layer 1002 whereas the second end securement section 1024 is exposed through gap 1000. In the next stage of 30 the process (Fig. 21h) the residual portion of copper layer 1004 remaining on the strip 1006 is removed in the connection portion 1026 of the strip, leaving the lead with first end securement section 1022, connection 35

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section 1026 and second end securement section 1024. Because second end securement section 1024 is connected to the dielectric support layer 1002 over only a very short length, and hence a very small area, and because 5 the second end securement section 1024 is unsupported by the underlayer 1016, the second end securement section can be detached readily from the support layer when the connection section 1026 is engaged by a bonding tool. Conversely, the first end securement section is securely 10 bonded to the dielectric support layer 1002 over a substantial length, and is supported by the underlayer 1016, so that the first end securement section is substantially permanently connected to the dielectric support layer.

15 In all of the embodiments illustrated above, the connection sections of the leads are bonded to contacts on the chip. However, similar components and methods can be used for bonding to a substrate or to another component of a semiconductor chip assemblage. 20 Such a variant is schematically shown in Fig. 22. The connection component 1200 has a dielectric supporting structure 1202 similar to those discussed above. The supporting structure 1202 defines gaps 1204. Numerous leads are provided, which only a few are shown in Fig. 25 22. Each lead has a connection section 1206 which, prior to assembly, extends across a gap 1204. Each lead also has a terminal 1208 remote from gap 1204. In the assembly procedure, the terminals 1208 are connected to terminals on a semiconductor chip 1210 whereas the 30 connection sections 1206 of the leads are connected to contacts 1212 on a chip mount, hybrid circuit panel or other supporting substrate 1214. The configurations of the connection sections 1206 may be similar to any of those discussed above. Also, the bonding procedures 35 used for bonding the connection sections to the contacts of the substrate may be essentially the same as those discussed above with reference to bonding to a chip. According to yet a further variant (not shown) the

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5 terminals 1208 may be replaced by a further set of connection sections and further gaps in the supporting structure. In this arrangement, each individual lead has two separate connection sections extending across two separate gaps in the supporting structure. The leads and gaps are configured so that when the connection component is disposed on an assemblage of a chip and substrate, one set of connection sections is positioned atop contacts on the chip, whereas another 10 set of connection sections, and the associated gaps, are positioned atop contacts on the substrate. In this arrangement, the bonding procedures discussed above may be used both for bonding the leads to the chip and for bonding the leads to the substrate.

15 A tape 1300 including a plurality of components in accordance with another embodiment of the invention is schematically depicted in Fig. 23. The tape includes a plurality of components each incorporating a support structure 1330. The support structure of each component incorporates a flexible, sheetlike dielectric layer 1332 as discussed above and may also include a soft, compliant layer similar to those discussed above, the compliant layer lying beneath the flexible dielectric layer 1332. The support 20 structure of each component has gaps 1340 extending through it from its top surface to its bottom surface so as to subdivide the support structure into an interior or central portion 1342 and an outer or peripheral portion 1344. The gaps merge with one another so that 25 the central or interior portion 1342 of each component is not connected to the outer or peripheral portion of the support structure by any other portion of the support structure. Rather, as discussed below, the central portion 1342 is temporarily connected to the outer or peripheral portion 1344 of the support 30 structure by the leads extending across gaps 1340. 35

The support structures of numerous components are formed as parts of the same continuous tape 1300.

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5        The outer or peripheral portions 1344 of the support structures of the various components, and particularly the outer or peripheral portions of the top dielectric layers 1332 are formed as parts of the same continuous piece of flexible dielectric film incorporated in the tape. The tape may be provided with features, such as the sprocket holes 1335, to facilitate feeding and movement of the tape in production processes.

10        Each component in accordance with this embodiment has a plurality of elongated electrically conductive buses 1353 extending on the peripheral portion 1344 of the top dielectric layer alongside slots 1340 so that one such bus extends alongside of, and substantially codirectionally with, each such slot. The 15        buses 1353 of each component form a generally rectilinear, hooplike structure encircling the gaps 1340 and the central portion 1342 of the support structure. Each component further has terminals 1348 disposed on the central portion 1342 of the support structure and a plurality of leads 1352 extending outwardly from the terminals. Each lead 1352 includes a first end 20        securement section 1366 on central portion 1342; a connection section 1356 extending outwardly across one of the gaps or slots 1340 from the first end securement section; a frangible section 1372 joined to the second or outer end 1362 of the connection section and a second end 25        securement section 1370 joining the frangible section to the bus 1353 lying alongside of the slot 1340. As shown in Fig. 24, the frangible sections 1372 lie just inside the outer margins of slots 1340. The 30        connection sections of all of the leads associated with any given slot extend generally perpendicular to the slot and generally side-by-side parallel to one another. In the condition illustrated, the connection sections 35        1356 and frangible sections 1372 of the leads bridge gaps 1340 and physically connect the central portion 1342 of the support structure with the peripheral portion 1344. Moreover, in this condition all of the

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leads, and hence, all of the terminals, are electrically connected to one another.

The dimensions and configuration of the lead will vary somewhat depending upon the materials of construction and depending upon the desired application. Leads having connection sections and frangible sections formed principally or entirely from gold may be employed. For gold or other noble metal leads with relatively small spacing between leads, the width  $w_1$  or dimension between the opposed edges of the lead in the direction transverse to the length of the connection section may be between about 15 microns and about 38 microns. The second end securement section 1370 may have a similar width. The frangible section 1372 of each lead may be defined by a pair of notches extending inwardly from the opposed edges of the lead. Each such notch may have a pair of angularly arranged edges defining a generally V-shaped notch with an included angle A (Fig. 24) desirably between about 45 degrees and about 120 degrees. The width  $w_2$  of the frangible section in the notch, i.e., the smallest dimension of the neck or frangible section in the direction transverse to the length of the connection section may be between about 5 microns and about 12 microns. Most preferably, the leads, including the connection sections have a thickness or vertical extent perpendicular to the plane of the dielectric layer 1332 (perpendicular to the plane of the drawings in Figs. 23 and 24) of about 10 to about 30 microns and most desirably about 25 microns. Preferably, each bus 1353 has a width  $w_3$ , i.e., the dimension transfers to the length of the bus, of at least about 50 microns and more preferably between about 50 and about 200 microns and a thickness of about 10 to about 30 microns and more preferably about 25 microns.

Components as illustrated in Fig. 23 and 24 may be formed by processes similar to those discussed above. Preferably, the process starts with a laminate including flexible layer 1330 with a thin film of copper

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deposited on the top surface. A photoresist is deposited on the copper, exposed to illumination in a pattern corresponding to the negative pattern of the desired leads and then subjected to processes to develop the photoresist. The undeveloped photoresist is then removed and a layer of gold in the thickness desired for the leads and buses is then plated on the copper in the areas left uncovered. This photoresist is then removed and the part is subjected to an etching process which removes the copper layer in those areas not covered by the gold of the buses and leads. Using a further mask, terminals 1348 are built up by further electroplating. In this electroplating process, the buses 1353 and leads 1352 provide electrical connections to the terminals 1348. Then, slots or gaps 1340 are formed by chemical etching or by laser etching dielectric film 1330. Formation of the slots or gaps leaves the lower surfaces of connection sections 1356 and frangible sections 1372, with portions of the initial copper layer thereon exposed. The component is then subjected to a further etching procedure to remove the copper from the lower surfaces of these parts, so that the connection sections and frangible sections are essentially devoid of copper. Some copper, however, is left beneath the first end attachment section 1366 and second end attachment section 1370 of each lead, and beneath each bus 1353, serving to anchor those parts to layer 1330. The component may be provided with the compliant layer 1334 beneath layer 1330 either at this point in the manufacturing process or when the component is assembled to the semiconductor chip.

The component of Figs. 23 - 25 may be employed with a semiconductor chip 1398 (Fig. 25) similar to those discussed above. Thus, the component is juxtaposed with the chip so that the central portion 1342 of the support structure overlies the central region of the chip, leaving slots 1340 and connection sections 1356 of the leads aligned with contacts 1301 on

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the chip. Compliant layer 1334 bears on the chip 1398. A support or ring 1304 encircling the chip may be provided to support the peripheral portion 1344 of the support structure. Leads 1356 are connected to contacts 1301 on the front face of the chip by a sequential bonding process similar to those discussed above. Thus, a bonding tool (not shown) is advanced downwardly into each slot 1340 so as to bond a lead to one contact, and the tool is then shifted sequentially along the slot with sequential bonding of various leads to the chip. During the bonding step, as the bonding tool engages each lead and forces it downwardly, the load applied to fracture the frangible section is distributed by the bus or a wide region of the support structure peripheral portion. This tends to maintain the second end securement section 1370 of each lead securely in position and thereby facilitates breakage of the frangible sections 1372. During the beginning part of this process, the central region 1340 of the support structure is held in place by the peripheral portion 1344 and by the leads connecting the central portion 1342 to the peripheral portion. Although each lead in and of itself is fragile, all of the leads together effectively secure the central portion in place. Buses 1353 substantially reinforce and stabilize the leads, and help to maintain the precise spacings between adjacent leads. As each lead is forced downwardly and bonded to the contact on the chip, its frangible section 1372 is broken thereby detaching the second end 1362 of its connection section 1356 from the bus, from the second end securement section 1370 of the lead and from the peripheral portion 1344 of the support structure. Thus, as the process continues the central portion is progressively detached from the peripheral portion and attached to the contacts of the chip. At each time during the process, however, the central portion is effectively held in place by the leads--first by the attachments of the leads to the peripheral portion, then

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by attachments of some leads to the peripheral portion and others to the chip and finally by attachment of the leads to the chip, leaving the central portion detached from the peripheral portion. After the bonding process, 5 the peripheral portion may be processed to reclaim the gold present in the buses.

During the lead-bonding operation, it may be desirable to crumple each lead slightly by displacing the tool, and the section of the lead engaged therewith, 10 towards the fixed or permanently connected end of the lead during the downward displacement and bonding steps, so as to form each lead into a generally S-shaped structure. This serves to limit or eliminate downward pull of the leads on the edge of the central or 15 permanent portion of the connection component.

Also, the bonding tool may be provided with guide surfaces capable of engaging and aligning leads extending in either of two orthogonal directions. Thus, instead of the generally blade-like tool illustrated in 20 Figs. 5 - 8 hereof, the tool may have a generally square lower end. The tool body may likewise define two orthogonal first and second axes extending through a central or bonding region of the lower end in first and second horizontal directions. The guide surfaces may 25 include a pair of first guide surfaces extending generally along the first axis, each such first guide surface flaring progressively outwardly, away from the first axis, with progressively increasing distance from the bonding region. Likewise, the body may further 30 define a pair of second guide surfaces extending along the second axis and flaring progressively outwardly, away from the second axis, with increasing distance from the bonding region. The first and second guide surfaces may be generally in the form of partial surfaces of 35 revolution about the first and second axes.

As these and other variations, combinations and modifications of the features discussed above can be employed without departing from the present invention,

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the foregoing description of the preferred embodiments should be taken by way of illustration rather than by way of limitation of the present invention as defined by the claims.

WHAT IS CLAIMED IS:

1. A semiconductor chip mounting component of the type having:

5 (a) a support structure having top and bottom surfaces and a gap extending through said support structure between said surfaces;

10 (b) a plurality of electrically conductive leads, characterized in that each such lead has a connection section extending across said gap and has first and second ends secured to support structure on opposite sides of said gap, the second end of each said connection section being secured to said support structure so that such second end can be displaced downwardly relative to said support structure responsive to a downward force applied to such connection section, said connection section of each said lead will be supported at both ends by said support structure during positioning of said component but each said connection section can be bent downwardly to engage a contact after 15 the component has been positioned on a part of a semiconductor chip assembly.

20 2. A component as claimed in claim 1 further characterized in that said support structure includes a dielectric layer defining said top surface, the component further comprising terminals disposed on said dielectric layer of said support structure and connected to said connection sections of said leads through the first ends of such connection sections.

25 3. A component as claimed in claim 2 further characterized in that said support structure includes resilient means for permitting downward displacement of said terminals.

30 35 4. A component as claimed in claim 3 further characterized in that said resilient means includes a layer of a compliant material disposed between said terminals and said bottom surface.

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5. A component as claimed in claim 1 wherein each said lead extends across said gap remote from said bottom surface.

5 6. A component as claimed in claim 1 wherein each said second end of each said lead is detachably secured to said support structure.

10 7. A component as claimed in claim 1 or claim 4 further characterized in that said gap includes at least one elongated slot, a plurality of said connection sections extending across each said slot.

8. A component as claimed in claim 7 further characterized in that said connection sections extending across said slot are substantially straight and parallel to one another.

15 9. A component as claimed in claim 8 further characterized in that said leads include some leads having said displaceable second ends of said connection sections adjacent a first edge of said slot and other leads having said displaceable second ends of said 20 connection section adjacent a second, opposite edge of said slot.

25 10. A component as claimed in claim 8 further characterized by an elongated bus disposed alongside each said elongated slot, the component further including frangible elements connecting the second ends of the connection sections extending across each said slot to the bus disposed alongside that slot.

30 11. A component as claimed in claim 8 further characterized in that each lead includes a frangible section, the connection section and frangible section of each lead being formed integrally with one another and with the associated bus, the connection section of each lead defining a pair of opposed horizontal edges, and further characterized in that the frangible section of 35 each lead has a pair of notches extending horizontally inwardly from said opposed edges to define a neck having width less than the width between said edges.

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12. A component as claimed in claim 11 further characterized in that each said lead has a second end securement section extending between the a frangible section and the associated bus, the second end securement section of each lead being formed integrally with the connection section, frangible section and the associated bus.

13. A component as claimed in claim 11 further characterized in that the width of each said lead between said opposed edges is between about 15 microns and about 40 microns, and further characterized in that the width of each said neck is between about 5 microns and about 12 microns.

14. A component as claimed in claim 11 further characterized in that each said notch is generally V-shaped and defines an included angle between about 45 and about 120 degrees.

15. A component as claimed in claim 11 further characterized in that each said bus is at least about 50 microns wide.

16. A component as claimed in claim 10 further characterized in that said support structure includes a central portion and a peripheral portion, said gap including a plurality of elongated slots extending substantially around said central portion so that the slots are disposed between the central portion and the peripheral portion, the component including a plurality of said elongated buses arranged on said peripheral portion so that one such bus extends alongside each said slot.

17. A component as claimed in claim 16 further characterized in that said buses are connected to one another so that said buses cooperatively form a hoop-like structure on said peripheral portion substantially surrounding said central portion and said slots.

18. A component as claimed in claim 17 further characterized in that said slots are connected

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to one another to form a substantially continuous channel surrounding said central portion, said central portion being connected to said peripheral portion only through said leads, whereby said central portion will 5 be detached from said peripheral portion upon breakage of said frangible elements.

19. A component as claimed in claim 1 further characterized in that said support structure includes a plurality of holes and said plurality of leads includes 10 at least one lead associated with each said hole.

20. A component as claimed in claim 1 further characterized in that each said lead has a second end 15 securement section and a frangible section connecting the second end of the connection section with the second end securement section, each said second end securement section being attached to said support structure, said second ends of said connection sections being attached to said support structure through said frangible sections of said leads.

21. A component as claimed in claim 1 or 20 claim 13 or claim 14 or claim 20 further characterized in that each said lead consists essentially of gold.

22. A component as claimed in claim 20 further characterized in that each said lead includes a 25 relatively thick structural metal layer, and a relatively thin first supplemental metal layer, the connection section and second end securement sections of each said lead including said structural metal layer, the frangible section of each said lead including said first supplemental metal layer but omitting said 30 structural metal layer.

23. A component as claimed in claim 20 further characterized in that the frangible section of each said lead includes a polymeric material.

35 24. A component as claimed in claim 1 further characterized in that said support structure includes a polymeric layer, each said lead extends only partially across said gap, the second end of the connection

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section of each said lead being disposed remote from said support structure, the component further including a polymeric strip associated with the connection section of each said lead and extending codirectionally therewith entirely across said gap, each said strip said polymeric strips being formed integrally with said polymeric layer of said support structure and secured to said support structure on both sides of the gap, the connection section of each said lead being fastened to the associated strip so that the second end of each said lead is secured to the support structure through the associated polymeric strip.

25. A component as claimed in claim 1 further characterized in that each said lead has a first end 15 securement section permanently bonded to said support structure on one side of the gap and a second end securement section releasably bonded to said support structure on the other side of the gap, the first and ends of each said connection section being connected to 20 the first end securement section and the second end securement section, respectively.

26. A semiconductor chip mounting component comprising:

(a) a support structure having top and bottom 25 surfaces and an edge;

(b) at least one electrically conductive lead, each said lead having a first end securement section mounted to said support structure and also having a connection section integral with said first end 30 securement section projecting beyond said edge of said support structure, each said connection section being flexible in a downward direction relative to said support structure to engage a contact; characterized by

(c) a flexible, polymeric reinforcement in 35 contact with said connection section of each said lead.

27. A component as claimed in claim 26 further characterized in that said polymeric reinforcement is in contact with each said lead at said

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edge, whereby said polymeric reinforcement will inhibit stress concentration in said lead at said edge.

28. A component as claimed in claim 27 further characterized in that said at least one lead 5 includes a plurality of leads, and wherein the connection section and first end securement section of each said lead include a unitary metallic strip, said polymeric reinforcement of each said lead including a polymeric strip extending codirectionally with such 10 metallic strip, the component further including a polymeric layer overlying said support structure, said polymeric strips being formed integrally with said polymeric layer.

29. A method of making connections to a part 15 of a semiconductor chip assembly characterized by the steps of:

(a) juxtaposing a connection component with 20 the chip so that a bottom surface of a support structure in said connection component confronts a front surface of a first part of such assembly having contacts on such surface, so that each contact on such front surface of such first part is aligned with a gap in such support structure and so that connection sections of leads on 25 said connection component extending across such gap are disposed above said contacts, said support structure supporting each said connection section at both sides of each such gap during the juxtaposing step; and

(b) bonding each said connection section to a 30 contact on said first part by displacing such connection section downwardly into the gap so as to displace one end of each said connection section downwardly relative to the support structure and bring the connection section into engagement with such contact.

30. A method as claimed in claim 29 further 35 characterized in that said bonding step is performed so as to detach said one end of each said connection section from said support structure during said downward displacement.

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31. A method as claimed in claim 30 wherein  
said bonding step includes the step of breaking a  
frangible portion of each said lead so as to detach one  
end of each connection section from said support  
5 structure by forcing the connection section downwardly  
with said bonding tool.

32. A method as claimed in claim 31 wherein  
the gap in said support structure includes at least one  
10 elongated slot, a plurality of said connection sections  
on said connection component extending across each said  
slot, said juxtaposing step being performed so that an  
elongated row of contacts on said first part is aligned  
with each said slot.

33. A method as claimed in claim 32 further  
15 characterized in that said gap includes a plurality of  
elongated slots connected to one another to form a  
substantially continuous channel extending around a  
central portion of the support structure and separating  
the central portion from a peripheral portion of the  
20 support structure so that prior to said bonding step the  
central portion is connected to the exterior portion  
solely through said leads, said step of detaching one  
end of each said connection section being performed so  
as to detach each said connection section from said  
25 central section, whereby the interior section is  
detached from the peripheral section during said  
connection step.

34. A method as claimed in claim 33 wherein  
said bonding step is performed so as to detach the  
30 connection sections of said leads from said peripheral  
section and bond said leads to the contacts on the part  
in sequence, so that each lead is bonded to the contacts  
on the part before the next lead is detached from the  
peripheral section, whereby the central portion of the  
35 support structure initially is connected to the  
peripheral portion through the connection sections of  
the leads, and then is connected by some leads to the  
peripheral portion and by other leads to the contact

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bearing part of the assembly and finally is severed from the peripheral portion.

35. A method as claimed in claim 32 or claim 33 or claim 34 wherein said connection component includes an elongated metallic bus extending alongside of each said slot adjacent to the frangible portions of said leads, and wherein said bus reinforces the support structure of the connection component prior to and during said bonding step.

10 36. A method as claimed in any one of claims 29 to 34 wherein said bonding step includes the step of engaging each said connection section with a recess in a bonding tool so that said bonding tool at least partially constrains the connection section during said 15 downward displacement.

37. A method as claimed in any one of claims 29 to 34 wherein said first part is a semiconductor chip and said connection sections of said leads are bonded to contacts on said chip in said bonding step.

20 38. A method of making connections to contacts on a front surface of a part of a semiconductor chip assembly comprising the steps of :

25 (a) juxtaposing a connection component with the part so that a bottom surface of a support structure in said connection component faces downwardly to the front surface of the part, and so that connection sections of a plurality of leads on said connection component extending from said support structure overly said contacts; and

30 (b) aligning said connection component with said part to thereby crudely align said connection sections of said leads with said contacts; characterized by the step of

35 (c) bonding said connection sections to said contacts on said part by engaging each said connection section with a bonding tool so that said bonding tool constrains the connection section into more precise alignment with the contact and displacing such bonding

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tool downwardly so as to force the connection section downwardly and bring the connection section into engagement with the aligned contact.

39. A method as claimed in claim 38 wherein  
5 each said connection section is in the form of an  
elongated strip, said part has said contacts disposed  
in at least one row, said connection component having a  
plurality of said connection sections extending  
substantially side-by-side and parallel to one another,  
10 said bonding step including the steps of after bonding  
each said connection section, raising said bonding tool  
and shifting said bonding tool along such row.

40. A method as claimed in claim 39 wherein  
15 said connection sections are disposed at center-to-  
center distances of less than about 0.5 mm.

41. A method as claimed in claim 39 or claim  
40 wherein said support structure supports each said  
connection section at both ends until engagement with  
said bonding tool.

42. A tool for bonding leads to contacts on a  
20 semiconductor chip comprising a body defining a bottom  
and a first groove extending in a lengthwise direction  
along said bottom for engaging leads to be bonded, and  
means for connecting said tool to a bonding apparatus so  
25 that said bottom of said tool faces downwardly.

43. A tool as claimed in claim 41 further  
characterized in that said first groove has a pair of  
30 sides extending lengthwise along the groove, a central  
plane between said sides and surfaces sloping upwardly  
from said sides toward said central plane so that said  
sloping surfaces will tend to guide a lead engaged  
therewith toward said central plane.

44. A tool as claimed in claim 42 or claim 43  
further characterized in that said body has a coupling  
35 portion on said bottom edge, said coupling portion  
having a lower surface adapted to bear on a lead engaged  
in said groove and a rough lower surface for coupling  
said tool to the lead.

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45. A method of making a semiconductor connection component comprising the steps of:

(a) providing an elongated conductive lead having a connecting section therein; and

5 (b) treating a dielectric support layer in contact with said lead so that said support layer has a gap in alignment with said connection section, said providing and treating steps being performed so that said connection section is permanently secured to said dielectric support layer on a first side of said gap and releasably secured to said dielectric support layer on a second side of said gap.

10 15 20 25 30 35 40 45 50 55 60 65 70 75 80 85 90 95 100 105 110 115 120 125 130 135 140 145 150 155 160 165 170 175 180 185 190 195 200 205 210 215 220 225 230 235 240 245 250 255 260 265 270 275 280 285 290 295 300 305 310 315 320 325 330 335 340 345 350 355 360 365 370 375 380 385 390 395 400 405 410 415 420 425 430 435 440 445 450 455 460 465 470 475 480 485 490 495 500 505 510 515 520 525 530 535 540 545 550 555 560 565 570 575 580 585 590 595 600 605 610 615 620 625 630 635 640 645 650 655 660 665 670 675 680 685 690 695 700 705 710 715 720 725 730 735 740 745 750 755 760 765 770 775 780 785 790 795 800 805 810 815 820 825 830 835 840 845 850 855 860 865 870 875 880 885 890 895 900 905 910 915 920 925 930 935 940 945 950 955 960 965 970 975 980 985 990 995 1000 1005 1010 1015 1020 1025 1030 1035 1040 1045 1050 1055 1060 1065 1070 1075 1080 1085 1090 1095 1100 1105 1110 1115 1120 1125 1130 1135 1140 1145 1150 1155 1160 1165 1170 1175 1180 1185 1190 1195 1200 1205 1210 1215 1220 1225 1230 1235 1240 1245 1250 1255 1260 1265 1270 1275 1280 1285 1290 1295 1300 1305 1310 1315 1320 1325 1330 1335 1340 1345 1350 1355 1360 1365 1370 1375 1380 1385 1390 1395 1400 1405 1410 1415 1420 1425 1430 1435 1440 1445 1450 1455 1460 1465 1470 1475 1480 1485 1490 1495 1500 1505 1510 1515 1520 1525 1530 1535 1540 1545 1550 1555 1560 1565 1570 1575 1580 1585 1590 1595 1600 1605 1610 1615 1620 1625 1630 1635 1640 1645 1650 1655 1660 1665 1670 1675 1680 1685 1690 1695 1700 1705 1710 1715 1720 1725 1730 1735 1740 1745 1750 1755 1760 1765 1770 1775 1780 1785 1790 1795 1800 1805 1810 1815 1820 1825 1830 1835 1840 1845 1850 1855 1860 1865 1870 1875 1880 1885 1890 1895 1900 1905 1910 1915 1920 1925 1930 1935 1940 1945 1950 1955 1960 1965 1970 1975 1980 1985 1990 1995 2000 2005 2010 2015 2020 2025 2030 2035 2040 2045 2050 2055 2060 2065 2070 2075 2080 2085 2090 2095 2100 2105 2110 2115 2120 2125 2130 2135 2140 2145 2150 2155 2160 2165 2170 2175 2180 2185 2190 2195 2200 2205 2210 2215 2220 2225 2230 2235 2240 2245 2250 2255 2260 2265 2270 2275 2280 2285 2290 2295 2300 2305 2310 2315 2320 2325 2330 2335 2340 2345 2350 2355 2360 2365 2370 2375 2380 2385 2390 2395 2400 2405 2410 2415 2420 2425 2430 2435 2440 2445 2450 2455 2460 2465 2470 2475 2480 2485 2490 2495 2500 2505 2510 2515 2520 2525 2530 2535 2540 2545 2550 2555 2560 2565 2570 2575 2580 2585 2590 2595 2600 2605 2610 2615 2620 2625 2630 2635 2640 2645 2650 2655 2660 2665 2670 2675 2680 2685 2690 2695 2700 2705 2710 2715 2720 2725 2730 2735 2740 2745 2750 2755 2760 2765 2770 2775 2780 2785 2790 2795 2800 2805 2810 2815 2820 2825 2830 2835 2840 2845 2850 2855 2860 2865 2870 2875 2880 2885 2890 2895 2900 2905 2910 2915 2920 2925 2930 2935 2940 2945 2950 2955 2960 2965 2970 2975 2980 2985 2990 2995 3000 3005 3010 3015 3020 3025 3030 3035 3040 3045 3050 3055 3060 3065 3070 3075 3080 3085 3090 3095 3100 3105 3110 3115 3120 3125 3130 3135 3140 3145 3150 3155 3160 3165 3170 3175 3180 3185 3190 3195 3200 3205 3210 3215 3220 3225 3230 3235 3240 3245 3250 3255 3260 3265 3270 3275 3280 3285 3290 3295 3300 3305 3310 3315 3320 3325 3330 3335 3340 3345 3350 3355 3360 3365 3370 3375 3380 3385 3390 3395 3400 3405 3410 3415 3420 3425 3430 3435 3440 3445 3450 3455 3460 3465 3470 3475 3480 3485 3490 3495 3500 3505 3510 3515 3520 3525 3530 3535 3540 3545 3550 3555 3560 3565 3570 3575 3580 3585 3590 3595 3600 3605 3610 3615 3620 3625 3630 3635 3640 3645 3650 3655 3660 3665 3670 3675 3680 3685 3690 3695 3700 3705 3710 3715 3720 3725 3730 3735 3740 3745 3750 3755 3760 3765 3770 3775 3780 3785 3790 3795 3800 3805 3810 3815 3820 3825 3830 3835 3840 3845 3850 3855 3860 3865 3870 3875 3880 3885 3890 3895 3900 3905 3910 3915 3920 3925 3930 3935 3940 3945 3950 3955 3960 3965 3970 3975 3980 3985 3990 3995 4000 4005 4010 4015 4020 4025 4030 4035 4040 4045 4050 4055 4060 4065 4070 4075 4080 4085 4090 4095 4100 4105 4110 4115 4120 4125 4130 4135 4140 4145 4150 4155 4160 4165 4170 4175 4180 4185 4190 4195 4200 4205 4210 4215 4220 4225 4230 4235 4240 4245 4250 4255 4260 4265 4270 4275 4280 4285 4290 4295 4300 4305 4310 4315 4320 4325 4330 4335 4340 4345 4350 4355 4360 4365 4370 4375 4380 4385 4390 4395 4400 4405 4410 4415 4420 4425 4430 4435 4440 4445 4450 4455 4460 4465 4470 4475 4480 4485 4490 4495 4500 4505 4510 4515 4520 4525 4530 4535 4540 4545 4550 4555 4560 4565 4570 4575 4580 4585 4590 4595 4600 4605 4610 4615 4620 4625 4630 4635 4640 4645 4650 4655 4660 4665 4670 4675 4680 4685 4690 4695 4700 4705 4710 4715 4720 4725 4730 4735 4740 4745 4750 4755 4760 4765 4770 4775 4780 4785 4790 4795 4800 4805 4810 4815 4820 4825 4830 4835 4840 4845 4850 4855 4860 4865 4870 4875 4880 4885 4890 4895 4900 4905 4910 4915 4920 4925 4930 4935 4940 4945 4950 4955 4960 4965 4970 4975 4980 4985 4990 4995 5000 5005 5010 5015 5020 5025 5030 5035 5040 5045 5050 5055 5060 5065 5070 5075 5080 5085 5090 5095 5100 5105 5110 5115 5120 5125 5130 5135 5140 5145 5150 5155 5160 5165 5170 5175 5180 5185 5190 5195 5200 5205 5210 5215 5220 5225 5230 5235 5240 5245 5250 5255 5260 5265 5270 5275 5280 5285 5290 5295 5300 5305 5310 5315 5320 5325 5330 5335 5340 5345 5350 5355 5360 5365 5370 5375 5380 5385 5390 5395 5400 5405 5410 5415 5420 5425 5430 5435 5440 5445 5450 5455 5460 5465 5470 5475 5480 5485 5490 5495 5500 5505 5510 5515 5520 5525 5530 5535 5540 5545 5550 5555 5560 5565 5570 5575 5580 5585 5590 5595 5600 5605 5610 5615 5620 5625 5630 5635 5640 5645 5650 5655 5660 5665 5670 5675 5680 5685 5690 5695 5700 5705 5710 5715 5720 5725 5730 5735 5740 5745 5750 5755 5760 5765 5770 5775 5780 5785 5790 5795 5800 5805 5810 5815 5820 5825 5830 5835 5840 5845 5850 5855 5860 5865 5870 5875 5880 5885 5890 5895 5900 5905 5910 5915 5920 5925 5930 5935 5940 5945 5950 5955 5960 5965 5970 5975 5980 5985 5990 5995 6000 6005 6010 6015 6020 6025 6030 6035 6040 6045 6050 6055 6060 6065 6070 6075 6080 6085 6090 6095 6100 6105 6110 6115 6120 6125 6130 6135 6140 6145 6150 6155 6160 6165 6170 6175 6180 6185 6190 6195 6200 6205 6210 6215 6220 6225 6230 6235 6240 6245 6250 6255 6260 6265 6270 6275 6280 6285 6290 6295 6300 6305 6310 6315 6320 6325 6330 6335 6340 6345 6350 6355 6360 6365 6370 6375 6380 6385 6390 6395 6400 6405 6410 6415 6420 6425 6430 6435 6440 6445 6450 6455 6460 6465 6470 6475 6480 6485 6490 6495 6500 6505 6510 6515 6520 6525 6530 6535 6540 6545 6550 6555 6560 6565 6570 6575 6580 6585 6590 6595 6600 6605 6610 6615 6620 6625 6630 6635 6640 6645 6650 6655 6660 6665 6670 6675 6680 6685 6690 6695 6700 6705 6710 6715 6720 6725 6730 6735 6740 6745 6750 6755 6760 6765 6770 6775 6780 6785 6790 6795 6800 6805 6810 6815 6820 6825 6830 6835 6840 6845 6850 6855 6860 6865 6870 6875 6880 6885 6890 6895 6900 6905 6910 6915 6920 6925 6930 6935 6940 6945 6950 6955 6960 6965 6970 6975 6980 6985 6990 6995 7000 7005 7010 7015 7020 7025 7030 7035 7040 7045 7050 7055 7060 7065 7070 7075 7080 7085 7090 7095 7100 7105 7110 7115 7120 7125 7130 7135 7140 7145 7150 7155 7160 7165 7170 7175 7180 7185 7190 7195 7200 7205 7210 7215 7220 7225 7230 7235 7240 7245 7250 7255 7260 7265 7270 7275 7280 7285 7290 7295 7300 7305 7310 7315 7320 7325 7330 7335 7340 7345 7350 7355 7360 7365 7370 7375 7380 7385 7390 7395 7400 7405 7410 7415 7420 7425 7430 7435 7440 7445 7450 7455 7460 7465 7470 7475 7480 7485 7490 7495 7500 7505 7510 7515 7520 7525 7530 7535 7540 7545 7550 7555 7560 7565 7570 7575 7580 7585 7590 7595 7600 7605 7610 7615 7620 7625 7630 7635 7640 7645 7650 7655 7660 7665 7670 7675 7680 7685 7690 7695 7700 7705 7710 7715 7720 7725 7730 7735 7740 7745 7750 7755 7760 7765 7770 7775 7780 7785 7790 7795 7800 7805 7810 7815 7820 7825 7830 7835 7840 7845 7850 7855 7860 7865 7870 7875 7880 7885 7890 7895 7900 7905 7910 7915 7920 7925 7930 7935 7940 7945 7950 7955 7960 7965 7970 7975 7980 7985 7990 7995 8000 8005 8010 8015 8020 8025 8030 8035 8040 8045 8050 8055 8060 8065 8070 8075 8080 8085 8090 8095 8100 8105 8110 8115 8120 8125 8130 8135 8140 8145 8150 8155 8160 8165 8170 8175 8180 8185 8190 8195 8200 8205 8210 8215 8220 8225 8230 8235 8240 8245 8250 8255 8260 8265 8270 8275 8280 8285 8290 8295 8300 8305 8310 8315 8320 8325 8330 8335 8340 8345 8350 8355 8360 8365 8370 8375 8380 8385 8390 8395 8400 8405 8410 8415 8420 8425 8430 8435 8440 8445 8450 8455 8460 8465 8470 8475 8480 8485 8490 8495 8500 8505 8510 8515 8520 8525 8530 8535 8540 8545 8550 8555 8560 8565 8570 8575 8580 8585 8590 8595 8600 8605 8610 8615 8620 8625 8630 8635 8640 8645 8650 8655 8660 8665 8670 8675 8680 8685 8690 8695 8700 8705 8710 8715 8720 8725 8730 8735 8740 8745 8750 8755 8760 8765 8770 8775 8780 8785 8790 8795 8800 8805 8810 8815 8820 8825 8830 8835 8840 8845 8850 8855 8860 8865 8870 8875 8880 8885 8890 8895 8900 8905 8910 8915 8920 8925 8930 8935 8940 8945 8950 8955 8960 8965 8970 8975 8980 8985 8990 8995 9000 9005 9010 9015 9020 9025 9030 9035 9040 9045 9050 9055 9060 9065 9070 9075 9080 9085 9090 9095 9100 9105 9110 9115 9120 9125 9130 9135 9140 9145 9150 9155 9160 9165 9170 9175 9180 9185 9190 9195 9200 9205 9210 9215 9220 9225 9230 9235 9240 9245 9250 9255 9260 9265 9270 9275 9280 9285 9290 9295 9300 9305 9310 9315 9320 9325 9330 9335 9340 9345 9350 9355 9360 9365 9370 9375 9380 9385 9390 9395 9400 9405 9410 9415 9420 9425 9430 9435 9440 9445 9450 9455 9460 9465 9470 9475 9480 9485 9490 9495 9500 9505 9510 9515 9520 9525 9530 9535 9540 9545 9550 9555 9560 9565 9570 9575 9580 9585 9590 9595 9600 9605 9610 9615 9620 9625 9630 9635 9640 9645 9650 9655 9660 9665 9670 9675 9680 9685 9690 9695 9700 9705 9710 9715 9720 9725 9730 9735 9740 9745 9750 9755 9760 9765 9770 9775 9780 9785 9790 9795 9800 9805 9810 9815 9820 9825 9830 9835 9840 9845 9850 9855 9860 9865 9870 9875 9880 9885 9890 9895 9900 9905 9910 9915 9920 9925 9930 9935 9940 9945 9950 9955 9960 9965 9970 9975 9980 9985 9990 9995 9999

48. A method as claimed in claim 45 or claim 46 or claim 47 wherein said step of selectively removing

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a portion of said dielectric support layer includes the step of etching said dielectric support layer.

49. A method as claimed in claim 45 wherein said step of providing said lead includes the step of providing a strip of a conductive structural material bonded to said dielectric support layer, and said step of treating said dielectric support layer includes the step of selectively removing a part of said dielectric support layer overlying a part of said strip to form said gap so that the part of said strip in alignment with said gap forms said connection section, and so that regions of said strip at opposite ends of said connection section remain bonded to said dielectric support layer on opposite sides of said gap to form first and second end securement sections, said first end securement section being more securely connected to said dielectric support layer than said second end securement section.

50. A method as claimed in claim 48 wherein said step of selectively removing a part of said dielectric layer to form said gap is performed so as to remove a part of said layer adjacent one end of said strip but remote from the other end of said strip so as to form said first end securement section as a relatively long portion of said strip and to form said second end securement section as a relatively short portion of said strip.

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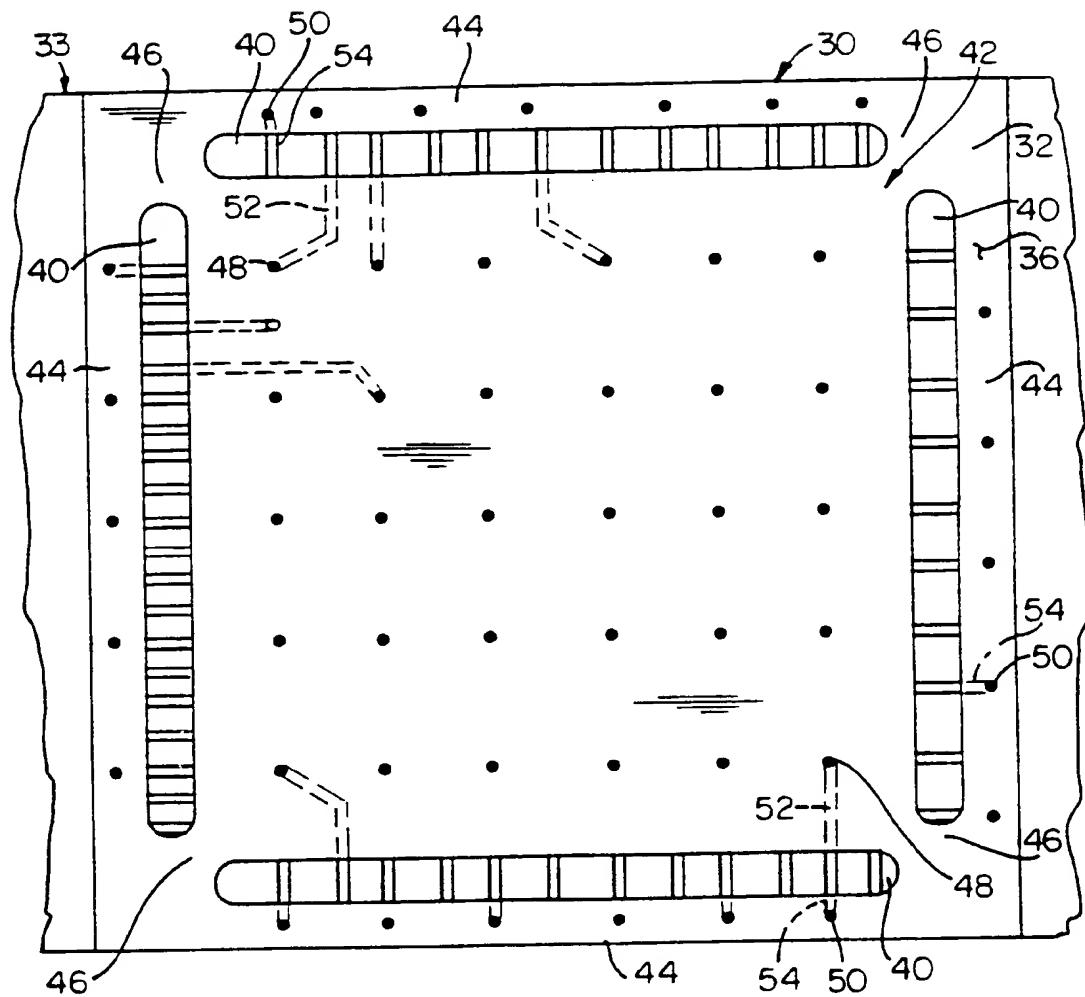


FIG. 1

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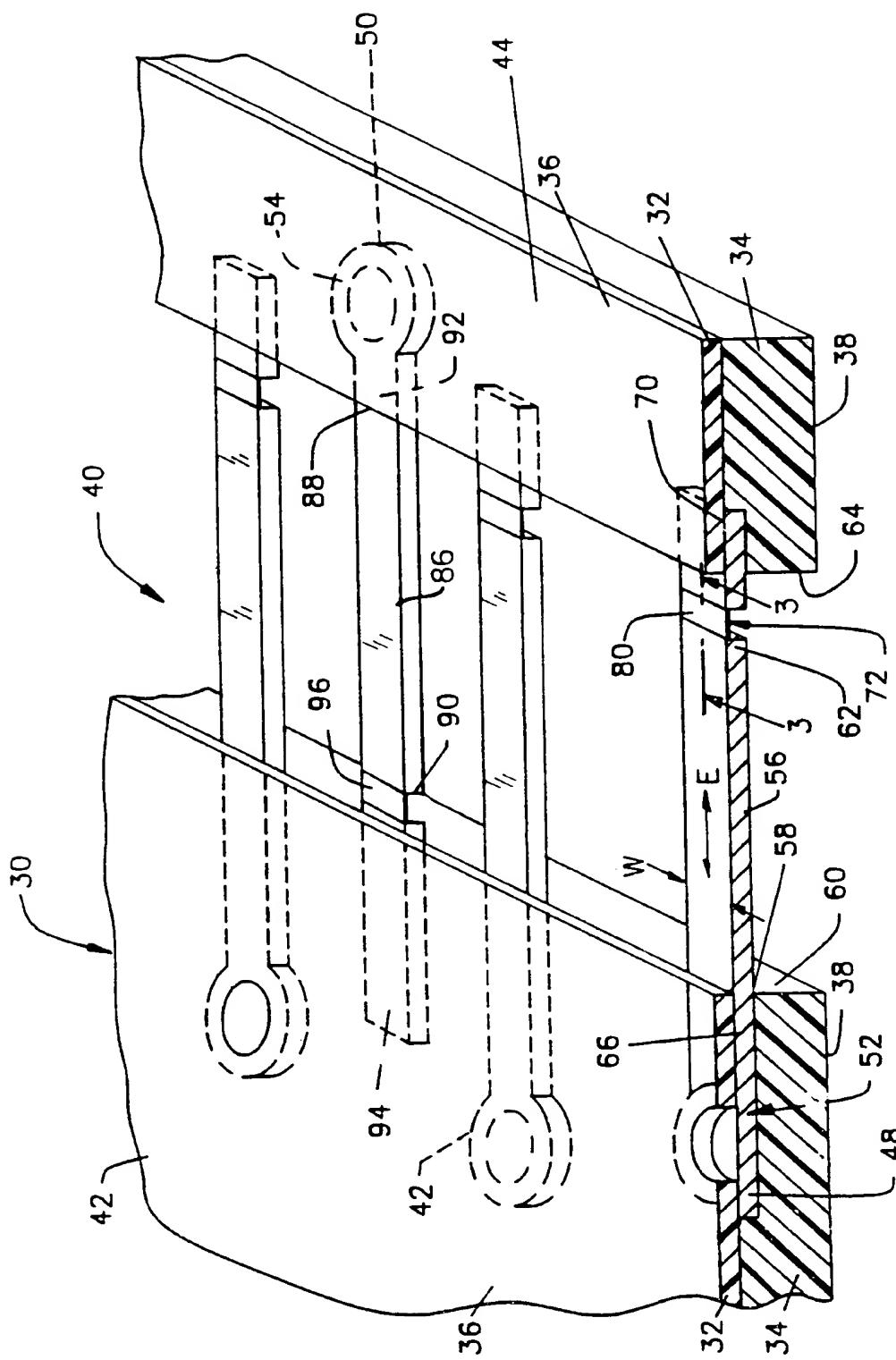


FIG. 2

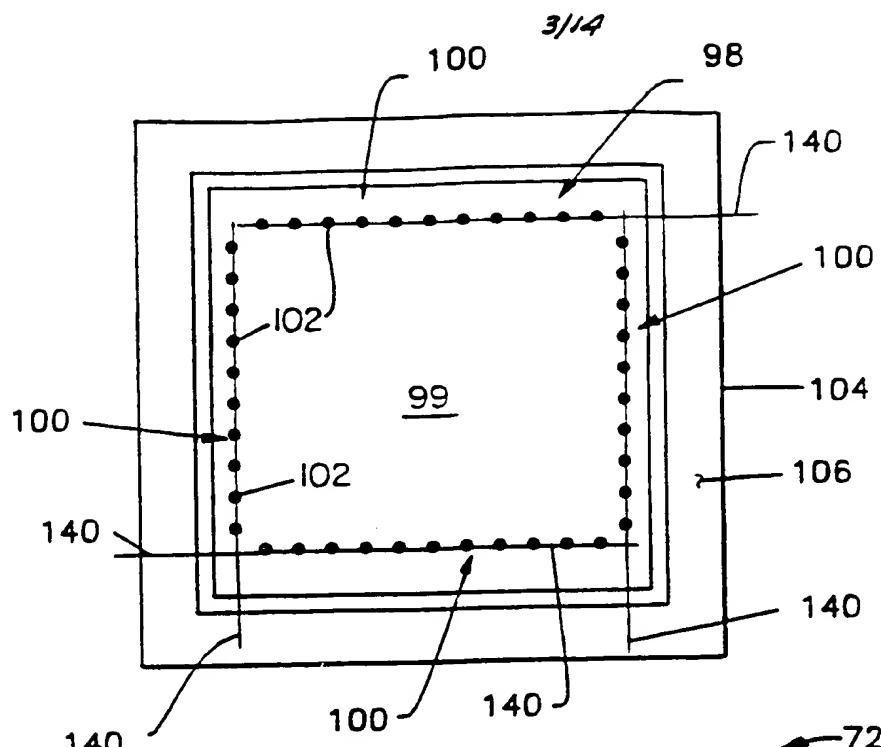


FIG. 4

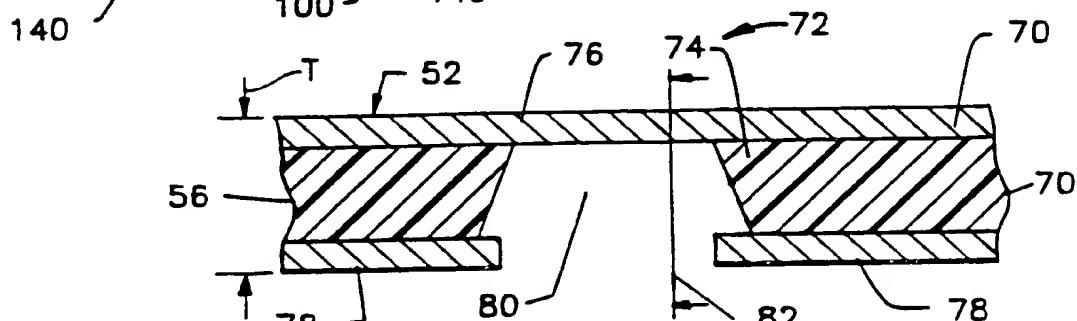


FIG. 3

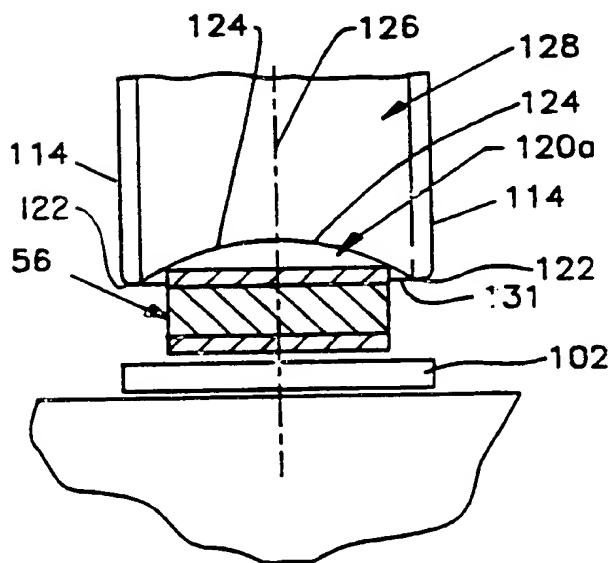
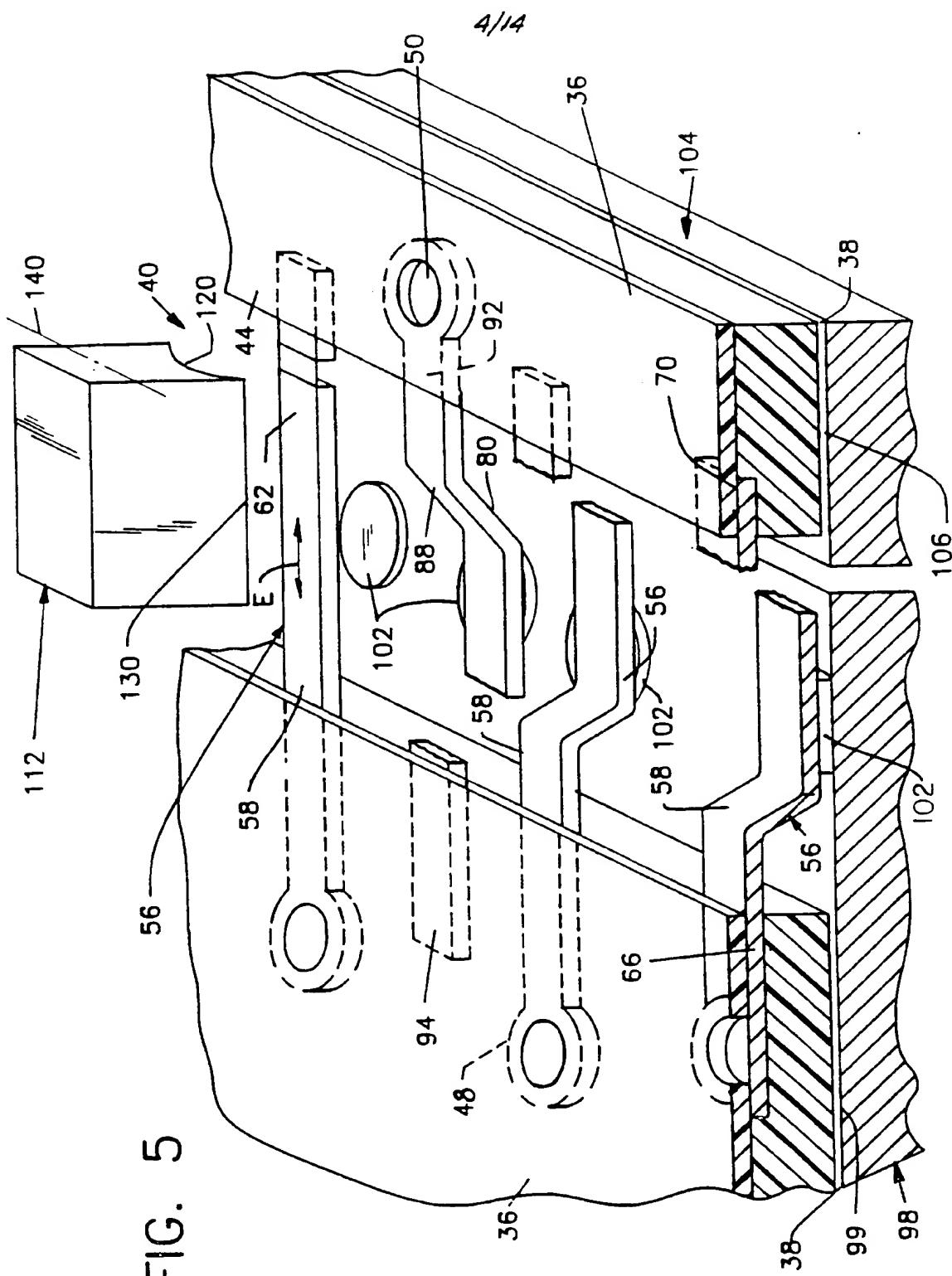
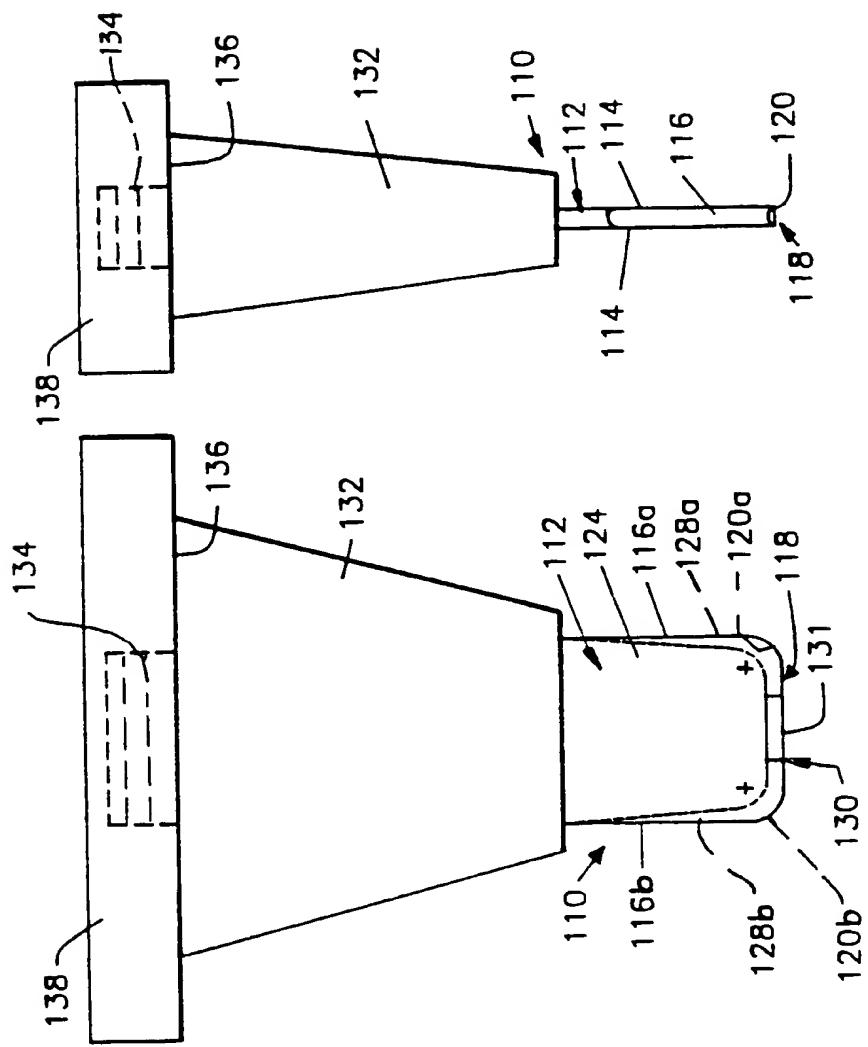


FIG. 8



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FIG.

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FIG. 6  
FIG. 7

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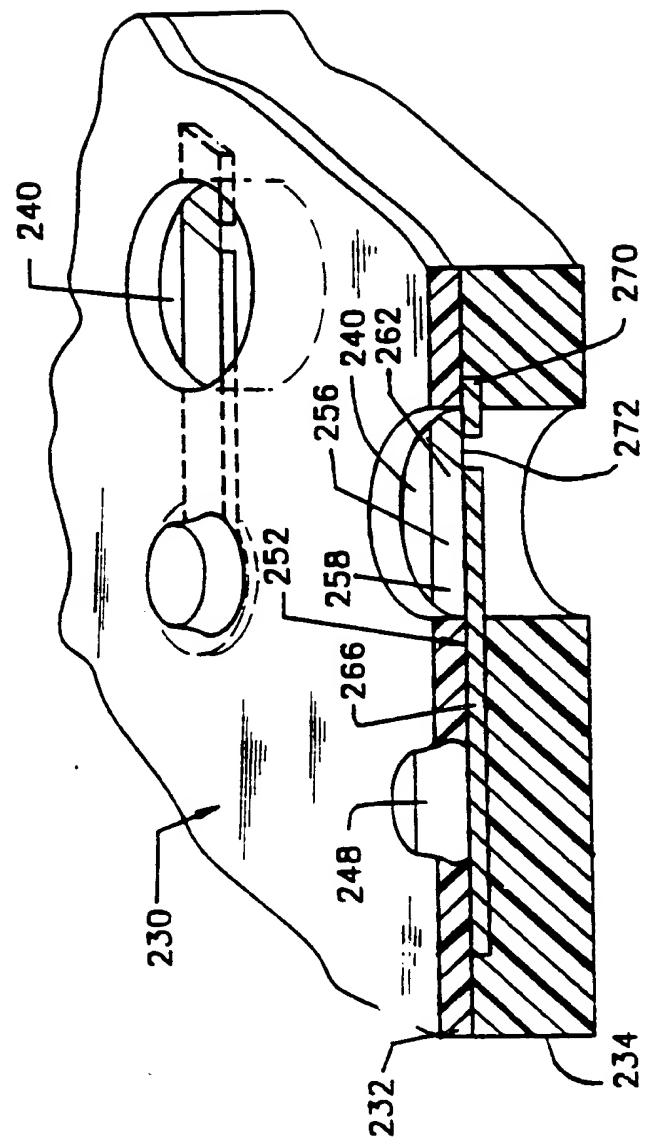
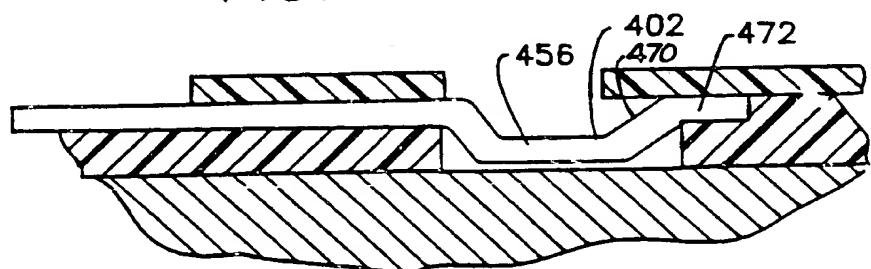
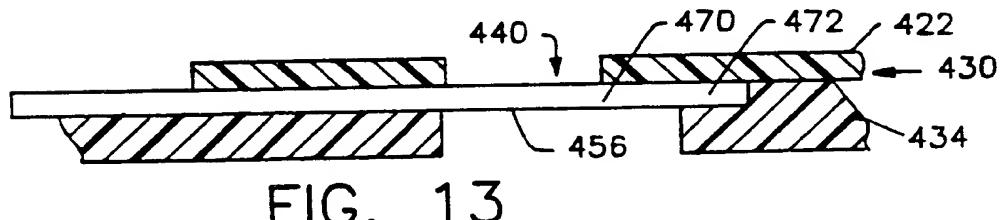
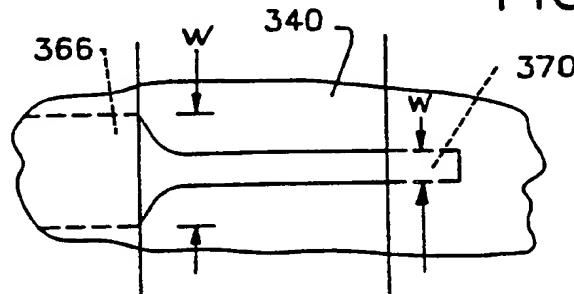
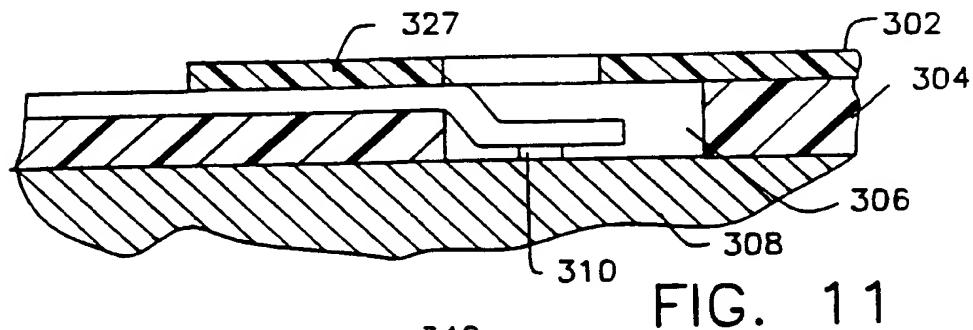
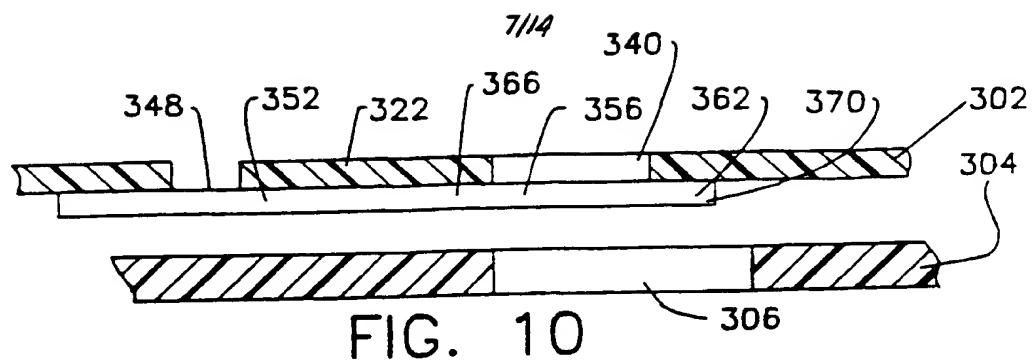


FIG. 9



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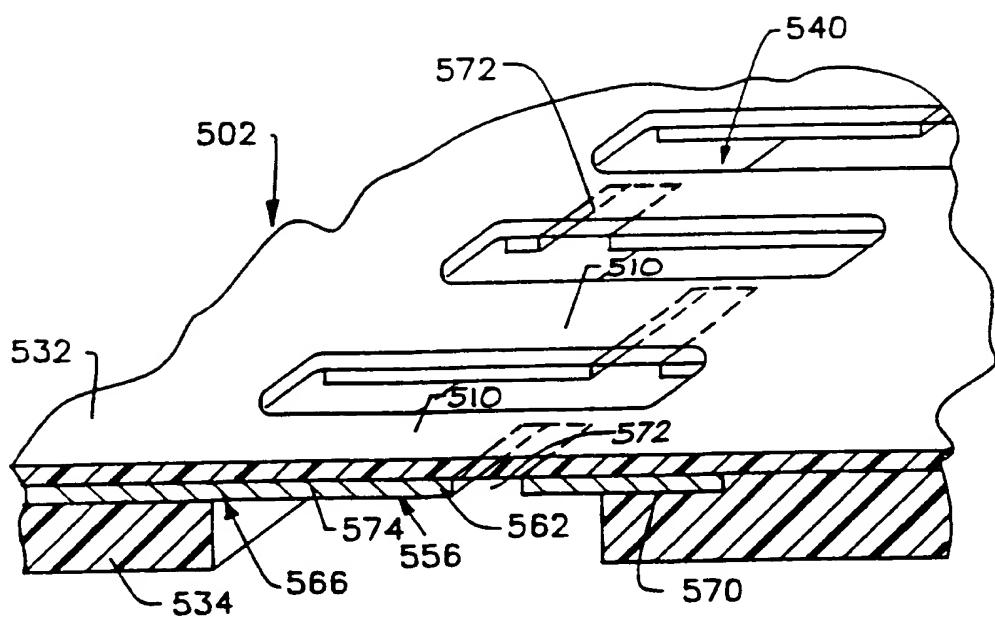


FIG. 15

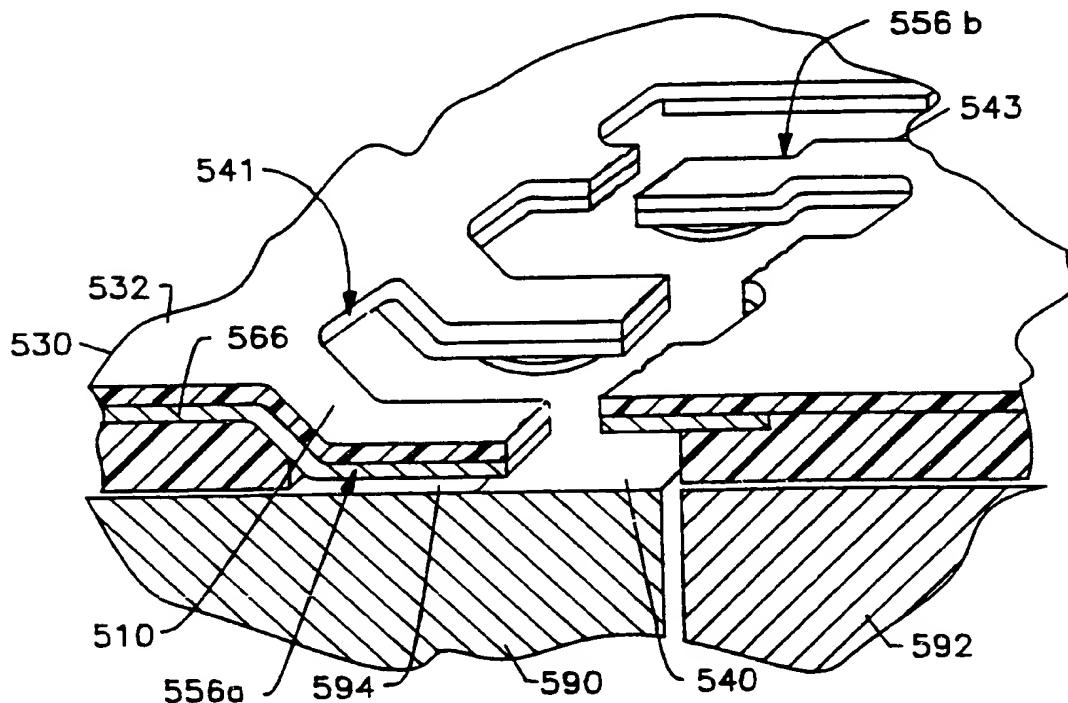
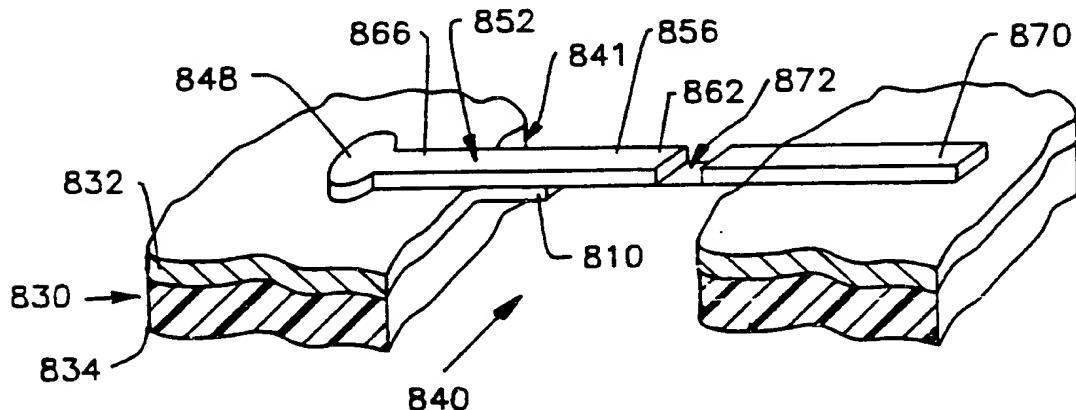
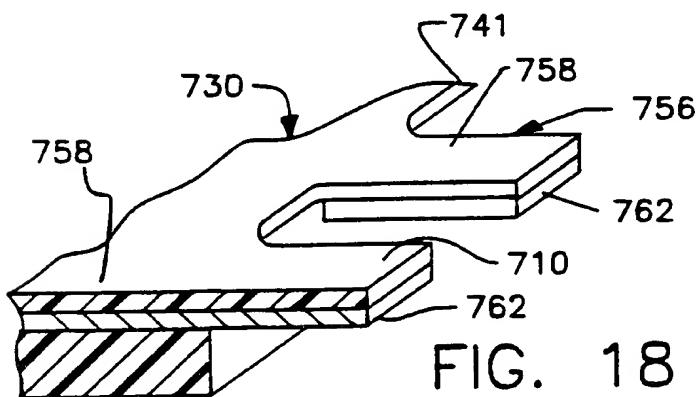
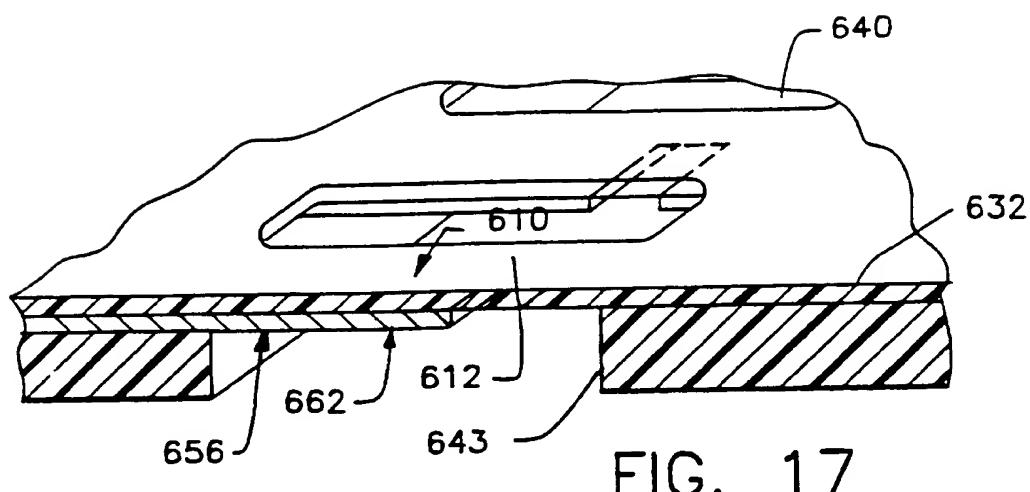


FIG. 16

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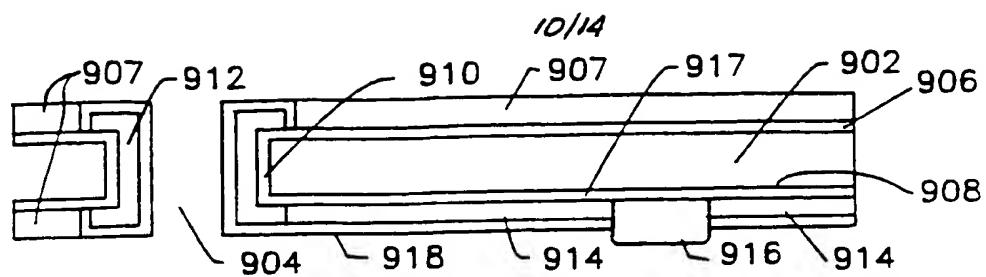


FIG. 20A

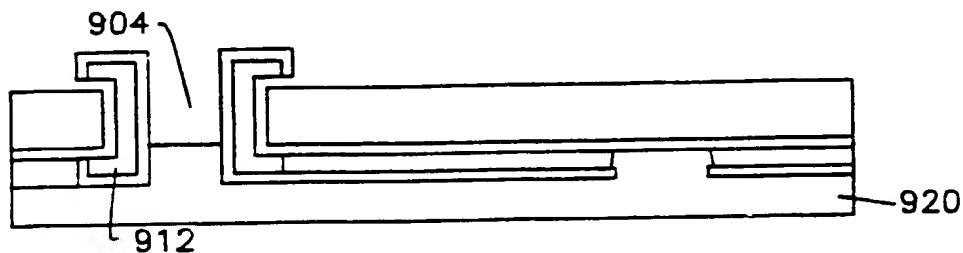


FIG. 20B

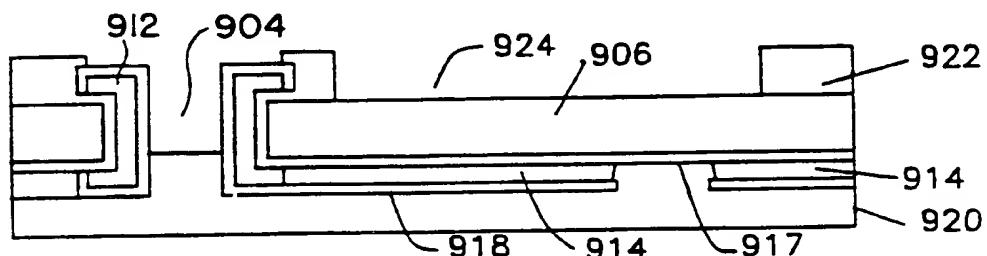


FIG. 20C

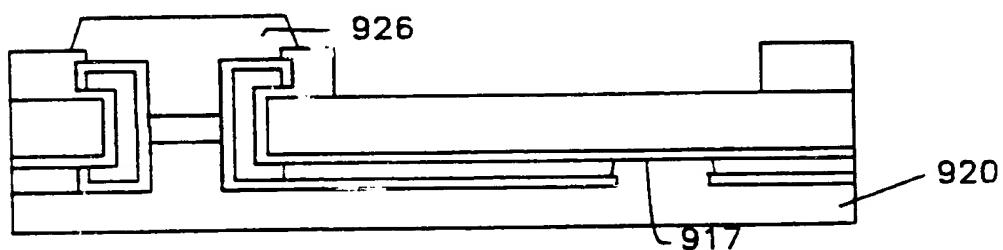


FIG. 20D

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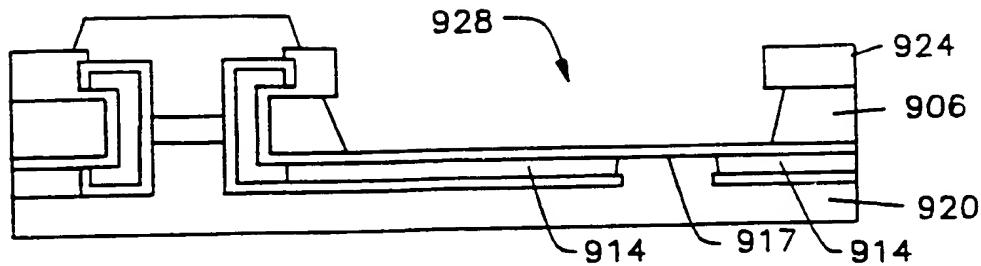


FIG. 20E

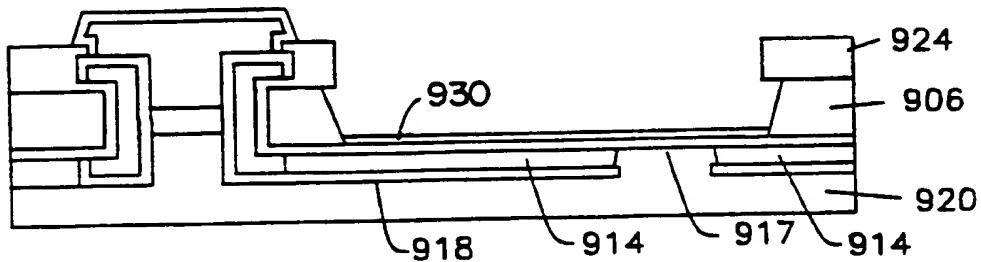


FIG. 20F

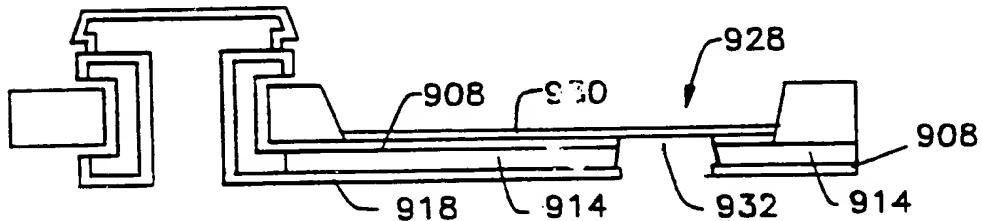


FIG. 20G

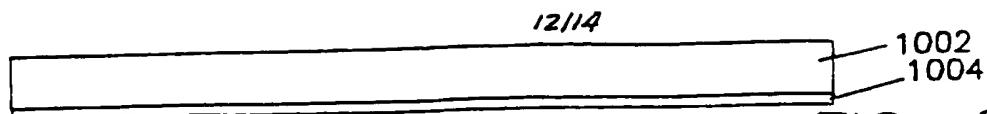


FIG. 21A

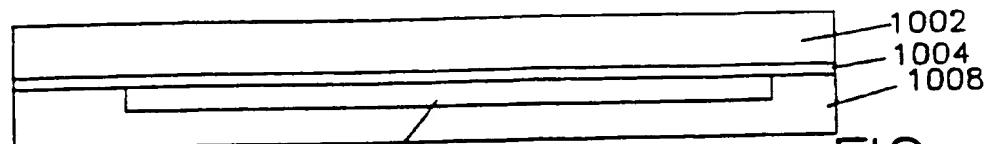


FIG. 21B

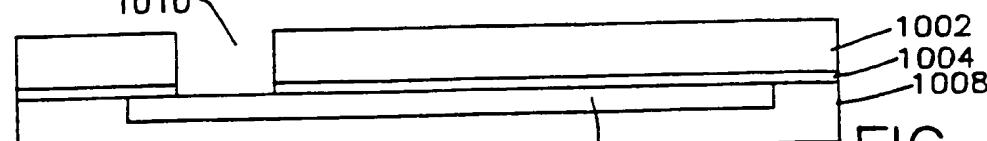


FIG. 21C

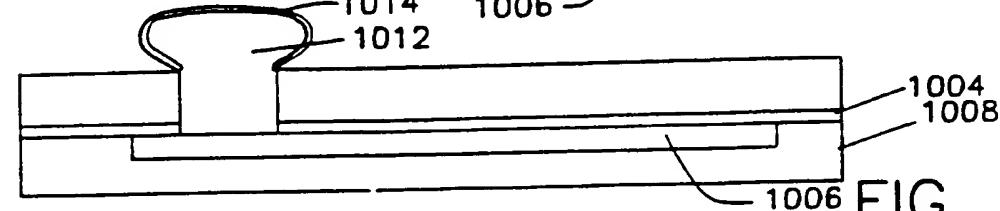


FIG. 21D

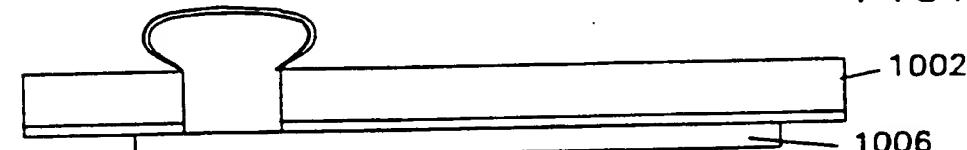


FIG. 21E

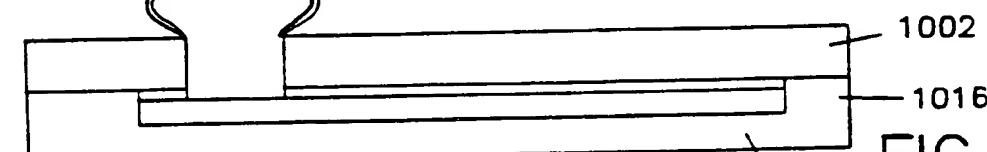


FIG. 21F

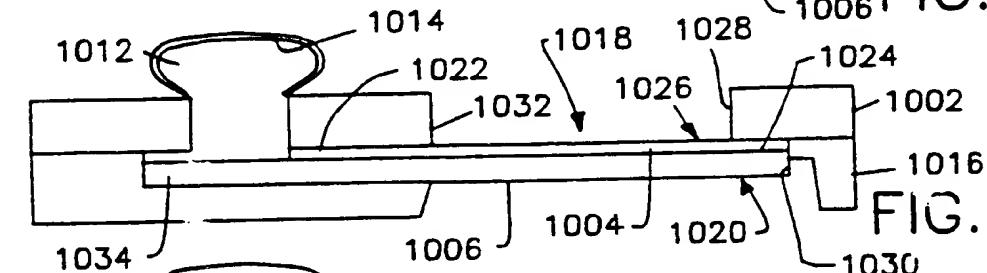


FIG. 21G

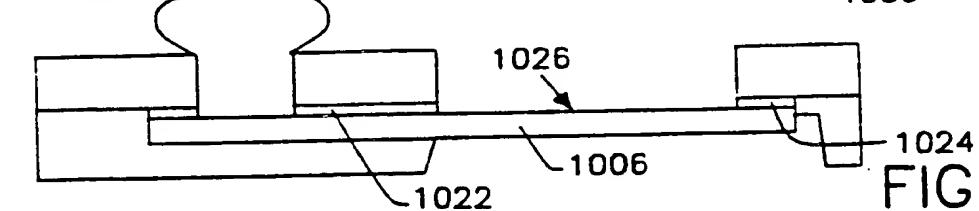


FIG. 21H

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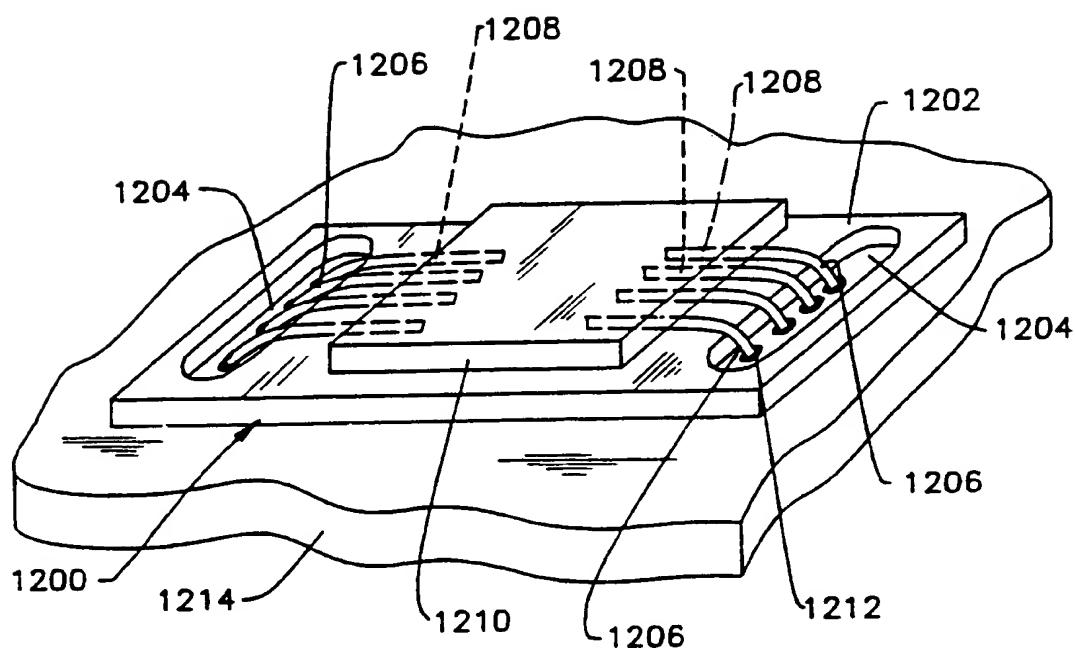


FIG. 22

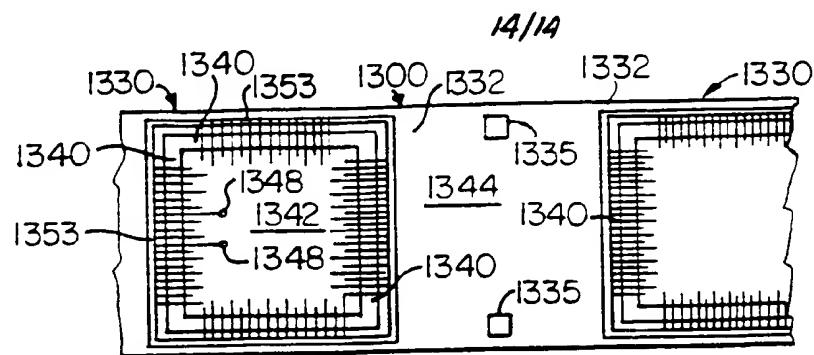


FIG. 23

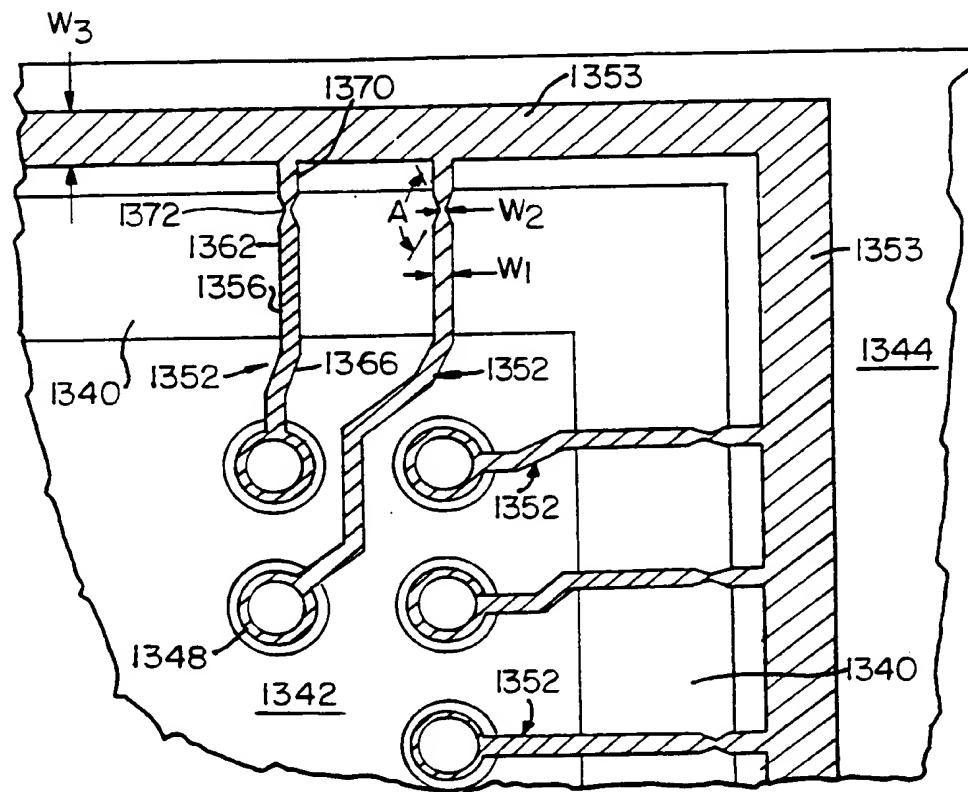


FIG. 24

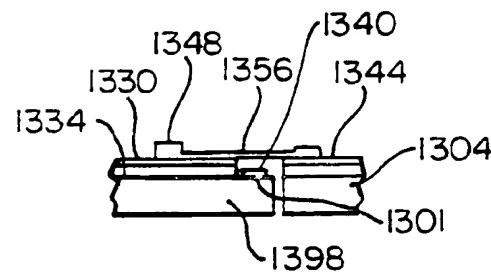


FIG. 25

## A. CLASSIFICATION OF SUBJECT MATTER

IPC(S) :H05K 3/36

US CL :174/261

According to International Patent Classification (IPC) or to both national classification and IPC

## B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

U.S. : 174/250, 260, 262, 267; 361/767, 770; 29/839, 845, 34R, 33F

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

## C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X, P Y	US, A, 5,177,863 (LAM) 12 January 1993, note Figures 1 and 2.	1-10, 16, 19 <u>20, 25, 45-46</u> 13, 21, 23, 26 27, 47-50
Y	US, A, 3,460,105 (BIRT ET AL.) 05 August 1969, note Figures.	47-50
X Y	US, A, 2,758,797 (MIKLAU) 14 August 1956, note Figure 1.	<u>42</u> 44
A	US, A4234,666 (GURSKY) 18 November 1980, note Figure 2.	1-50
A	US, A, 3,374,537 (DOELP, JR.) 26 March 1968, note figure 2.	1-50

 Further documents are listed in the continuation of Box C. See patent family annex.

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*E* earlier document published on or after the international filing date	"Y"	document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art
*L* document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reasons (as specified)	"Z"	document member of the same patent family
*O* document referring to an oral disclosure, use, exhibition or other means		
*P* document published prior to the international filing date but later than the priority date claimed		

Date of the actual completion of the international search

19 NOVEMBER 1993

Date of mailing of the international search report

DEC 02 1993

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## C (Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	US, A, 5,173,574 (KRAUS) 22 December 1992, note figures 1-5.	1-50
A, E	US, A, 5,252,784 (ASAI ET AL.) 12 October 1993, note figure 1.	1-50
A	US, A, 4,859,806 (SMITH) 22 August 1989, note figure 3.	1-50
A, P	US, A, 5,225,633 (WIGGINTON) 06 July 1993, note figure 7.	1-50

## Box I Observations where certain claims were found unsearchable (Continuation of item 1 of first sheet)

This international report has not been established in respect of certain claims under Article 17(2)(a) for the following reasons:

1.  Claims Nos.: because they relate to subject matter not required to be searched by this Authority, namely:
  
2.  Claims Nos.: because they relate to parts of the international application that do not comply with the prescribed requirements to such an extent that no meaningful international search can be carried out, specifically:
  
3.  Claims Nos.: because they are dependent claims and are not drafted in accordance with the second and third sentences of Rule 6.4(a).

## Box II Observations where unity of invention is lacking (Continuation of item 2 of first sheet)

This International Searching Authority found multiple inventions in this international application, as follows:

Group I: Claims 1-28 drawn to a semiconductor chip mounting component

Group II: Claims 29-41 drawn to a method of making connections to a part of a semiconductor chip.

Group III: Claims 42-44 drawn to a bonding tool.

Group IV: Claims 45-50 drawn to a method of making a semiconductor connection component.

1.  As all required additional search fees were timely paid by the applicant, this international search report covers all searchable claims.
2.  As all searchable claims could be searched without effort justifying an additional fee, this Authority did not invite payment of any additional fee.
3.  As only some of the required additional search fees were timely paid by the applicant, this international search report covers only those claims for which fees were paid, specifically claims Nos.:
  
4.  No required additional search fees were timely paid by the applicant. Consequently, this international search report is restricted to the invention first mentioned in the claims; it is covered by claims Nos.:

Remark on Protest

The additional search fees were accompanied by the applicant's protest.

No protest accompanied the payment of additional search fees.